

COMPAL CONFIDENTIAL

MODEL NAME : **IBQ00**

PCB NO : **LA-3302P (DAA00000K0L)**

BOM P/N : **45144731L01**

M08 (DIS) Briscoe

**uFCPGA Mobile Merom
Intel Crestline + ICH8M**

2007 - 03 - 07

REV : 0.4 (X03)

**@ : Nopop Component
1@ : Populate for G72MV
2@ : Populate for G86MV
45144731L01 pop for G86MV
45144XXXXX pop for G72MV**

MB PCB	
Part Number	Description
DAA00000K0L	PCB ZGX LA-3302P REV0 N/B DIS

hexainf@hotmail.com
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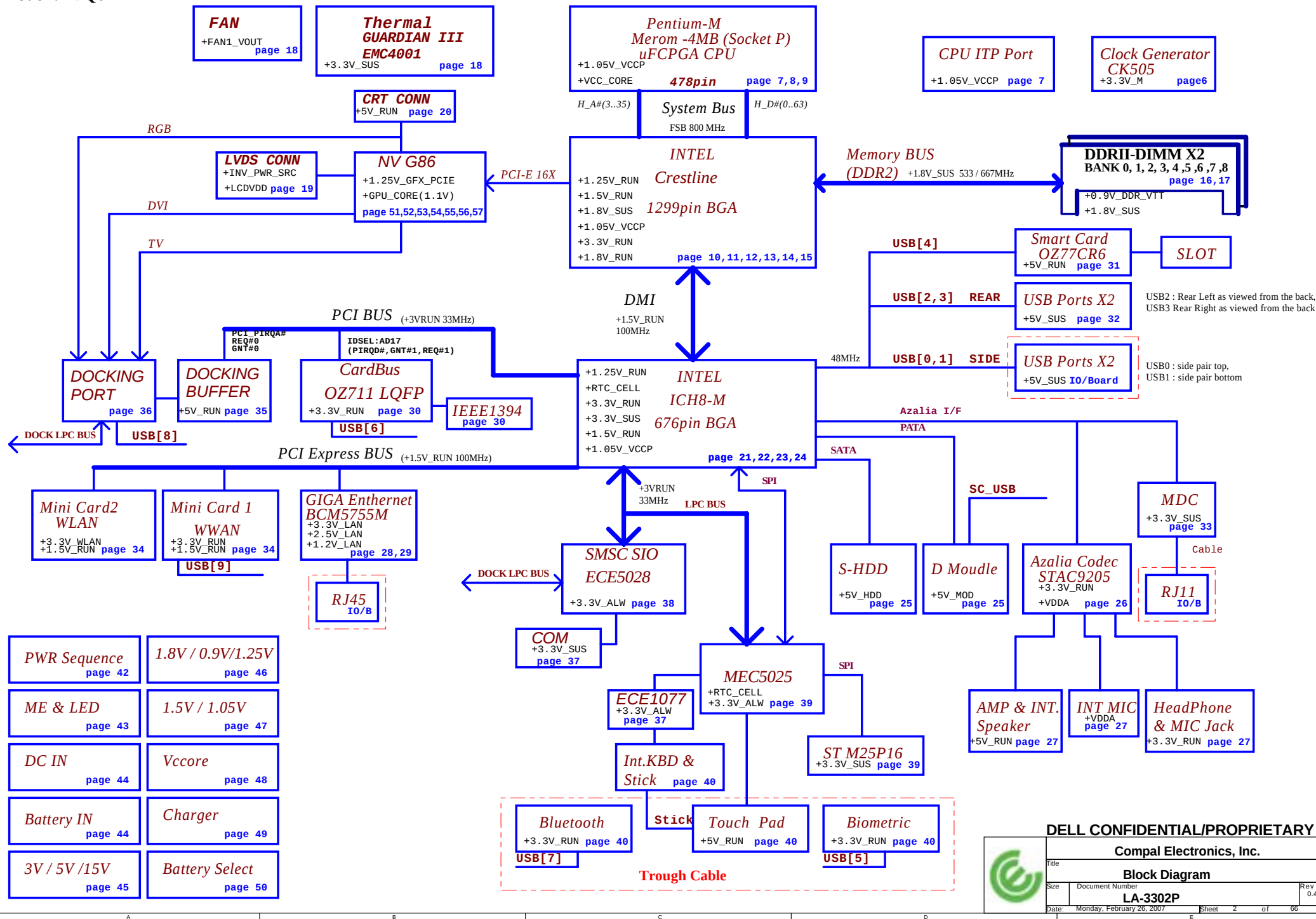


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Block Diagram
Compal confidential
Model : IBQ01



POWER STATES

Signal State	SLP S3#	SLP S4#	SLP S5#	S4 STATE#	SLP M#	ALWAYS PLANE	M PLANE	SUS PLANE	RUN PLANE	CLOCKS
S0 (Full ON) / M0	HIGH	HIGH	HIGH	HIGH	HIGH	ON	ON	ON	ON	ON
S3 (Suspend to RAM) / M1	LOW	HIGH	HIGH	HIGH	HIGH	ON	ON	ON	OFF	ON
S4 (Suspend to DISK) / M1	LOW	HIGH	HIGH	LOW	HIGH	ON	ON	ON	OFF	ON
S5 (SOFT OFF) / M1	LOW	HIGH	LOW	LOW	HIGH	ON	ON	ON	OFF	ON
S3 (Suspend to RAM) / M-OFF	LOW	HIGH	HIGH	HIGH	LOW	ON	OFF	ON	OFF	OFF
S4 (Suspend to DISK) / M-OFF	LOW	LOW	HIGH	LOW	LOW	ON	OFF	OFF	OFF	OFF
S5 (SOFT OFF) / M-OFF	LOW	LOW	LOW	LOW	LOW	ON	OFF	OFF	OFF	OFF

PM TABLE

power plane State	+15V_ALW +5V_ALW +3.3V_ALW +3.3V_RTC_LDO	+5V_SUS +3.3V_SUS +1.8V_SUS	+5V_RUN +3.3V_RUN +2.5V_RUN +1.8V_RUN +1.5V_RUN +VCC_+1P2V_GPU_CORE +0.9V_DDR_VTT +GPU_CORE +VCC_CORE +1.05V_VCCP	+3.3V_M +1.25V_M +1.05V_M	+1.25V_M +3.3V_M +1.05V_M (M-OFF)
S0	ON	ON	ON	ON	ON
S3	ON	ON	OFF	ON	OFF
S5 S4/AC	ON	OFF	OFF	ON	OFF
S5 S4/AC don't exist	OFF	OFF	OFF	OFF	OFF

PCI TABLE

PCI DEVICE	IDSEL	REQ#/GNT#	PIRQ
OZ711	AD17	REQ#1 / GNT#1	PIRQD
Docking	AD24	REQ#0 / GNT#0	PIRQA

ICH8-M	USB PORT#	DESTINATION
	0	Side Top
	1	Side Bottom
	2	Rear Left
	3	Rear Right
	4	Smart Card
	5	Biometric
	6	Card Bus
	7	Bluetooth
	8	Docking
ECE 5028	9	WWAN
	1	None
	2	None
	3	None
	4	None

PCI EXPRESS	DESTINATION
Lane 1	MINI CARD-1 WWAN
Lane 2	MINI CARD-2 WLAN
Lane 3	None
Lane 4	None
Lane 5	None
Lane 6	GIGA LAN

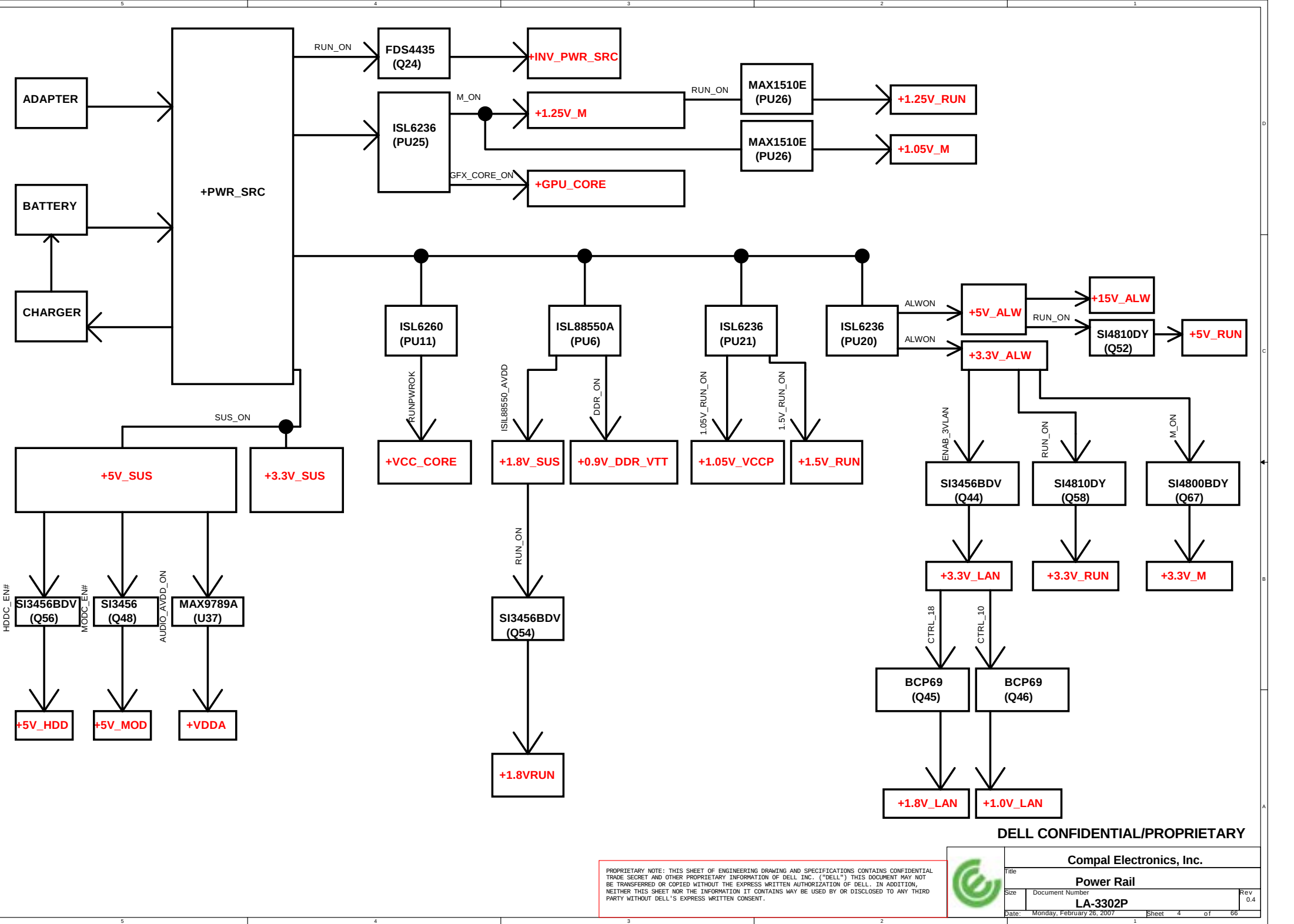
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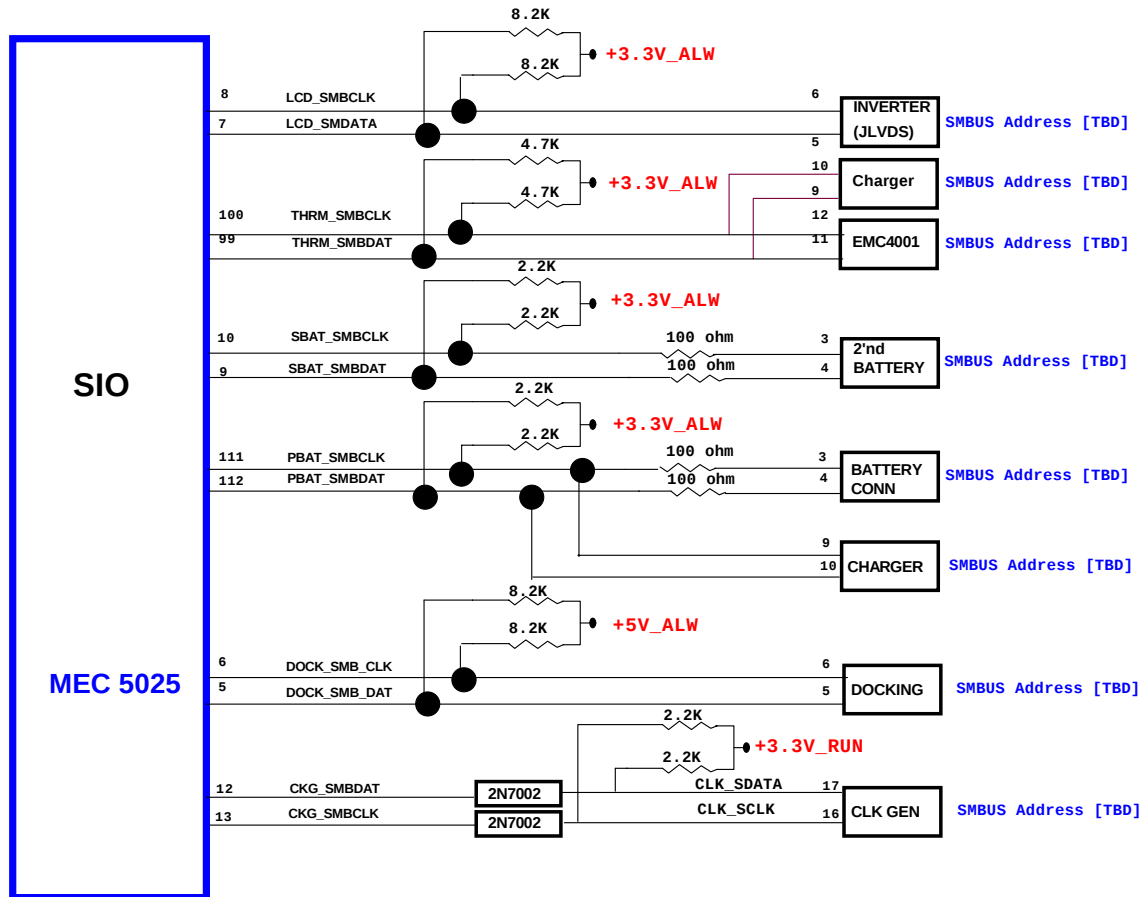
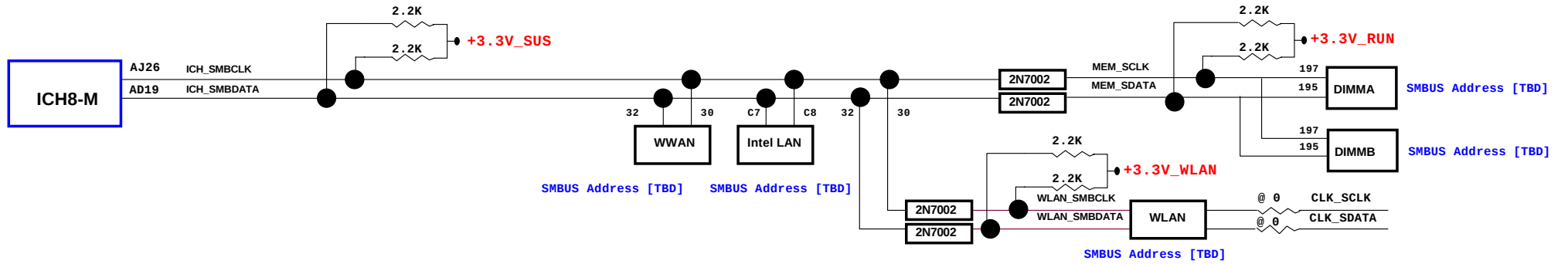


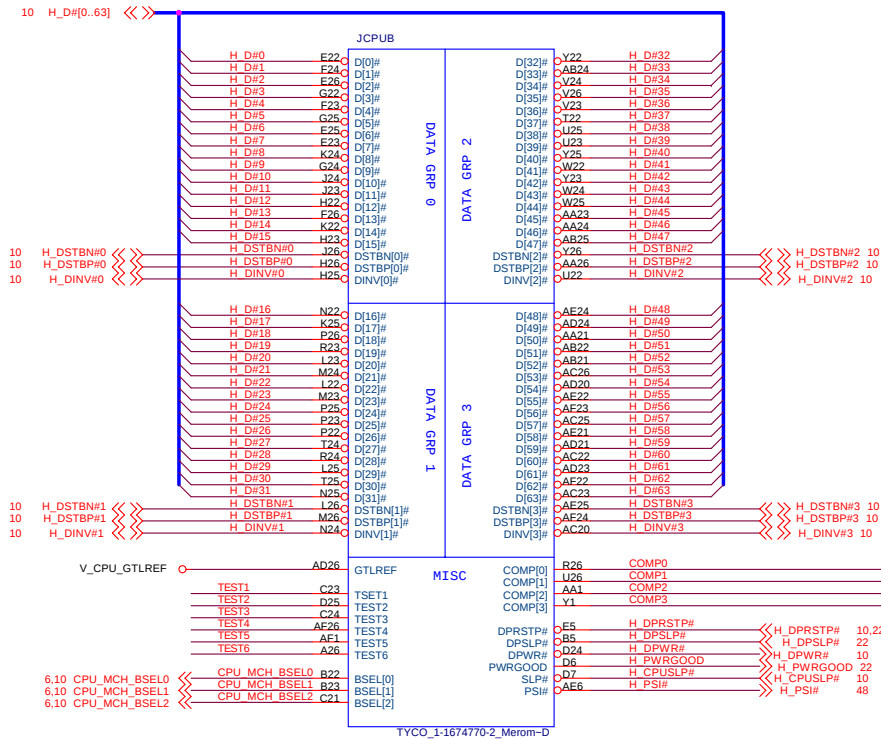
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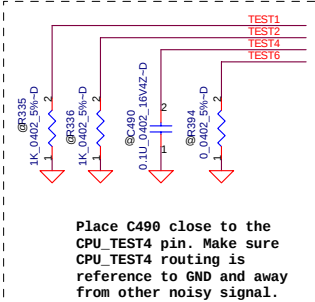


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Power Rail			
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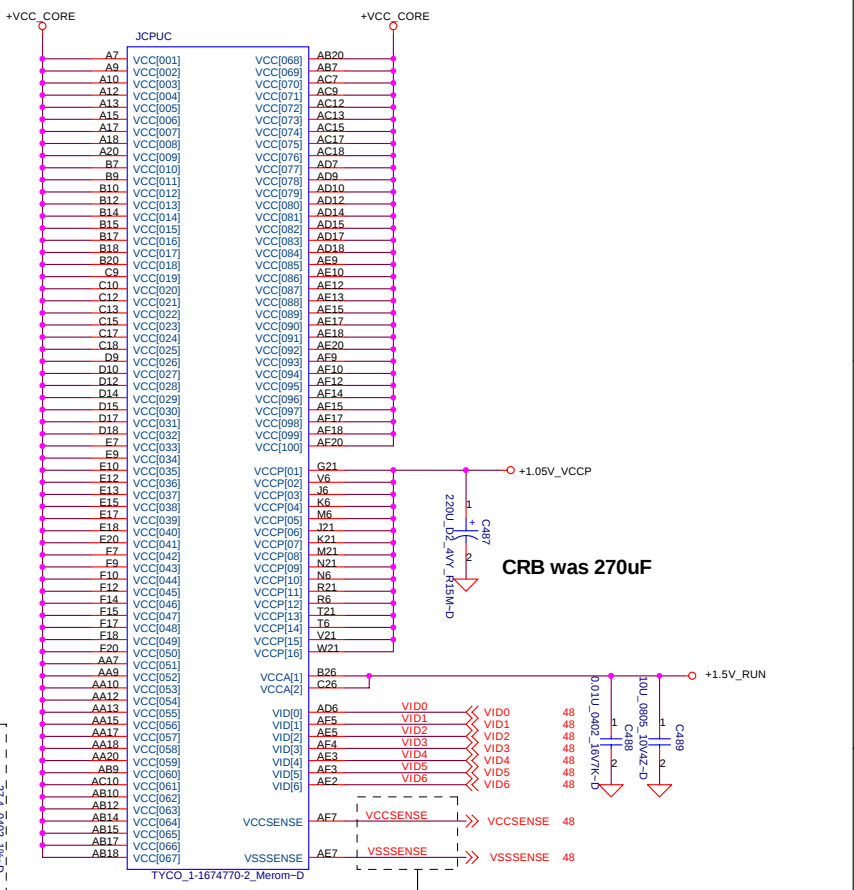
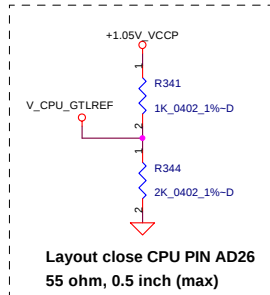


Resistor placed within 0.5" of CPU pin. Trace should be at least 25 mils away from any other toggling signal. COMP0, COMP2 trace should be 27.4 ohm. COMP1, COMP3 should be 55 ohm.

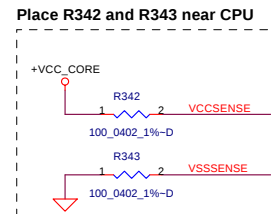


For the purpose of testability, route these signals through a ground referenced Z0 = 55ohm trace that ends in a via that is near a GND via and is accessible through an oscilloscope connection.

FSB	BCLK	BSEL2	BSEL1	BSEL0
533	133	0	0	1
667	166	0	1	1
800	200	0	1	0



Length match within 25 mils, Z0=27.4 ohm



Route VCCSENSE and VSSSENSE trace at 27.4 ohms, 7 mils spacing and 1 inch (max)

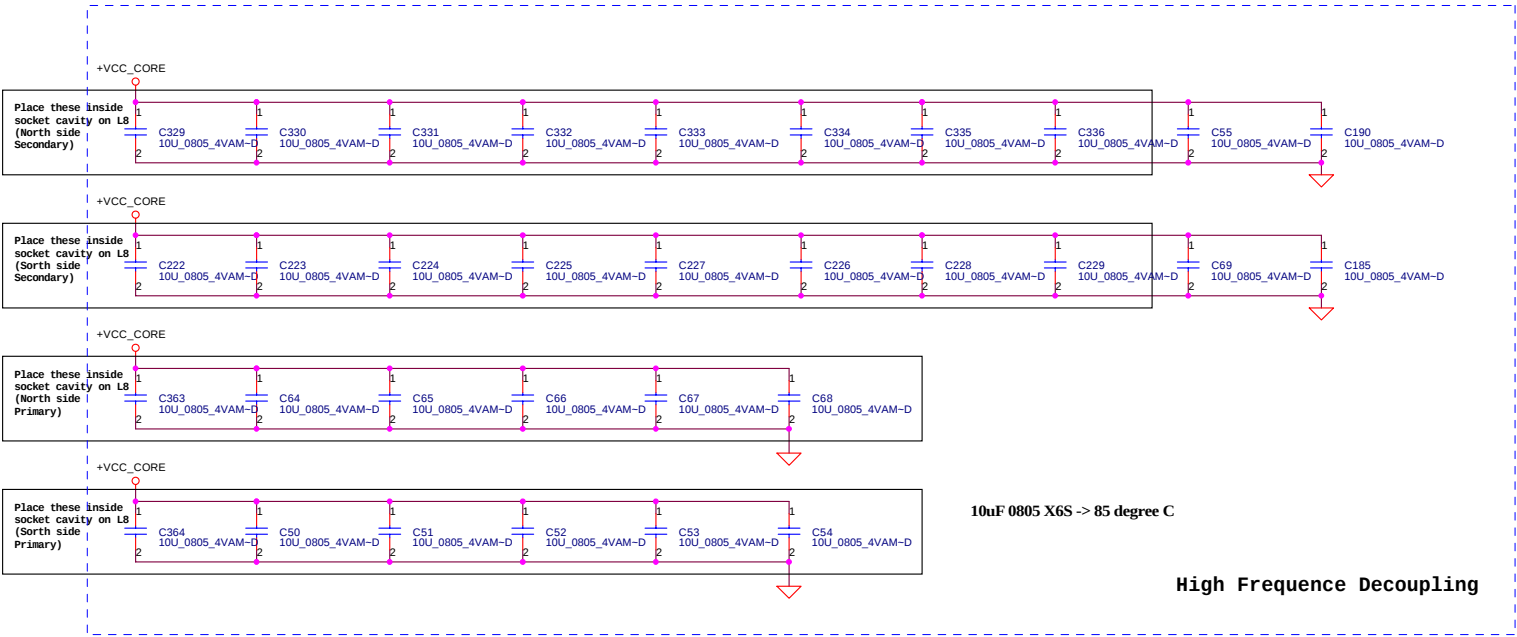
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Merom Processor(2/2)

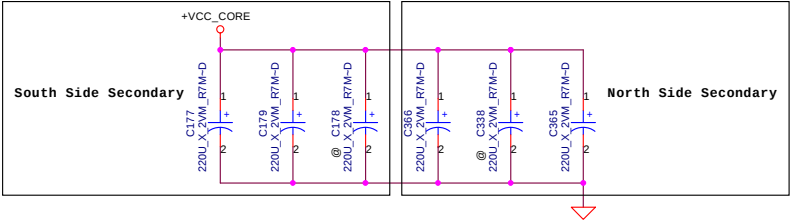
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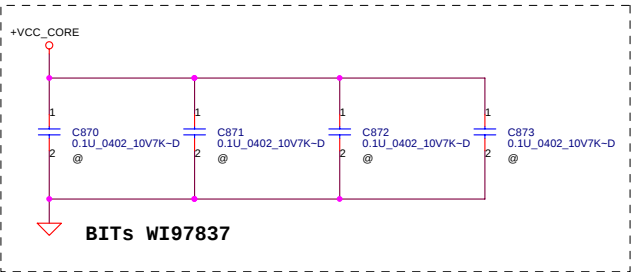


High Frequency Decoupling

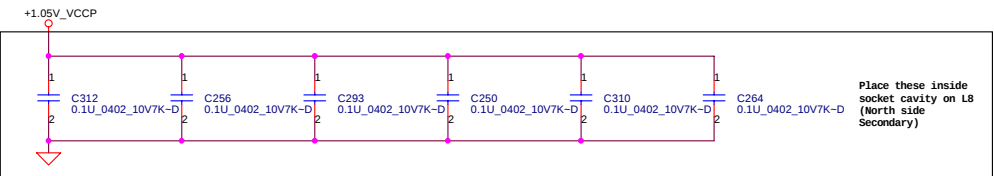
Near VCORE regulator.



ESR <= 1.5m ohm
Capacitor > 1980uF



BITS WI97837



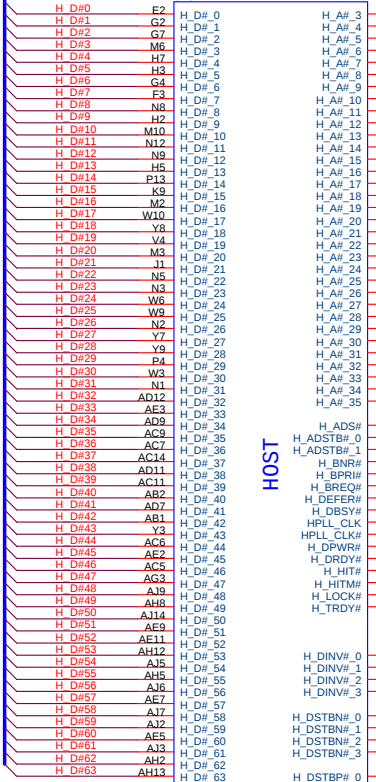
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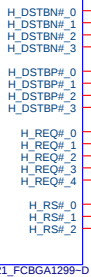
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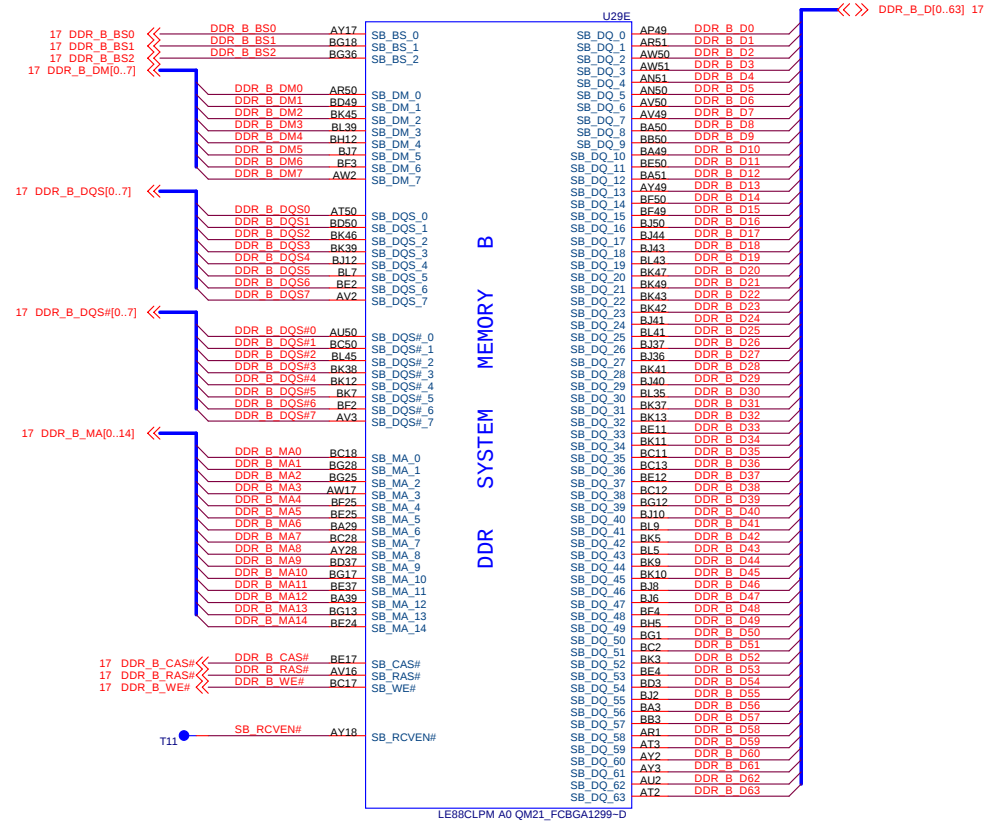
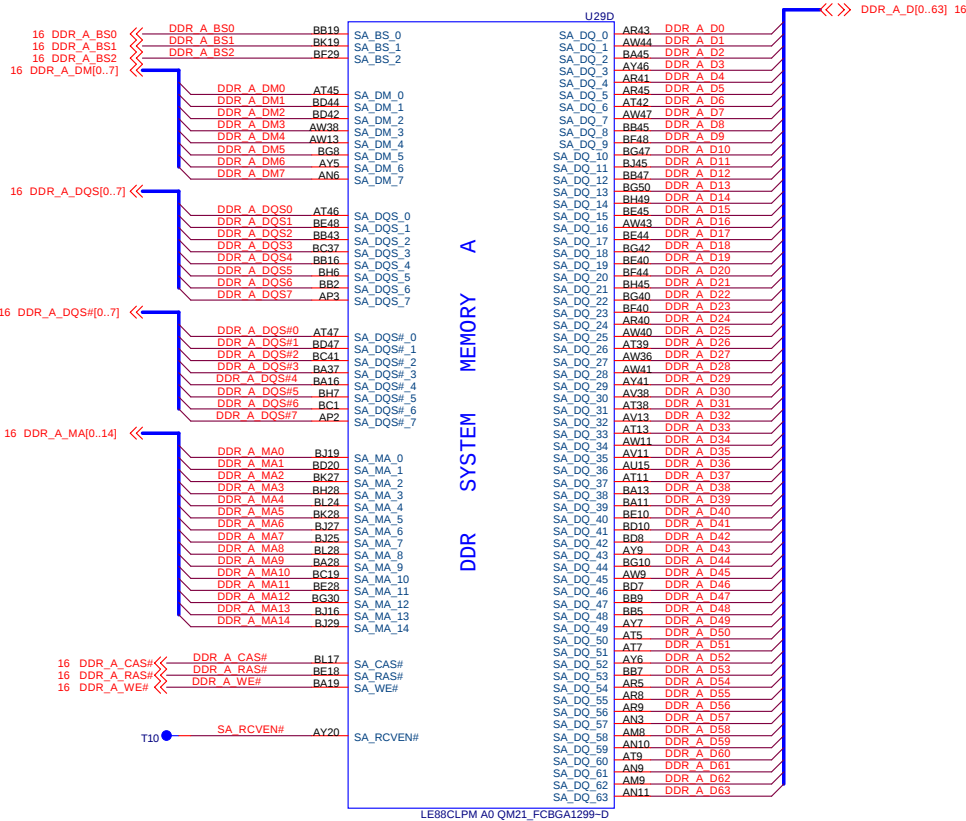
HOST

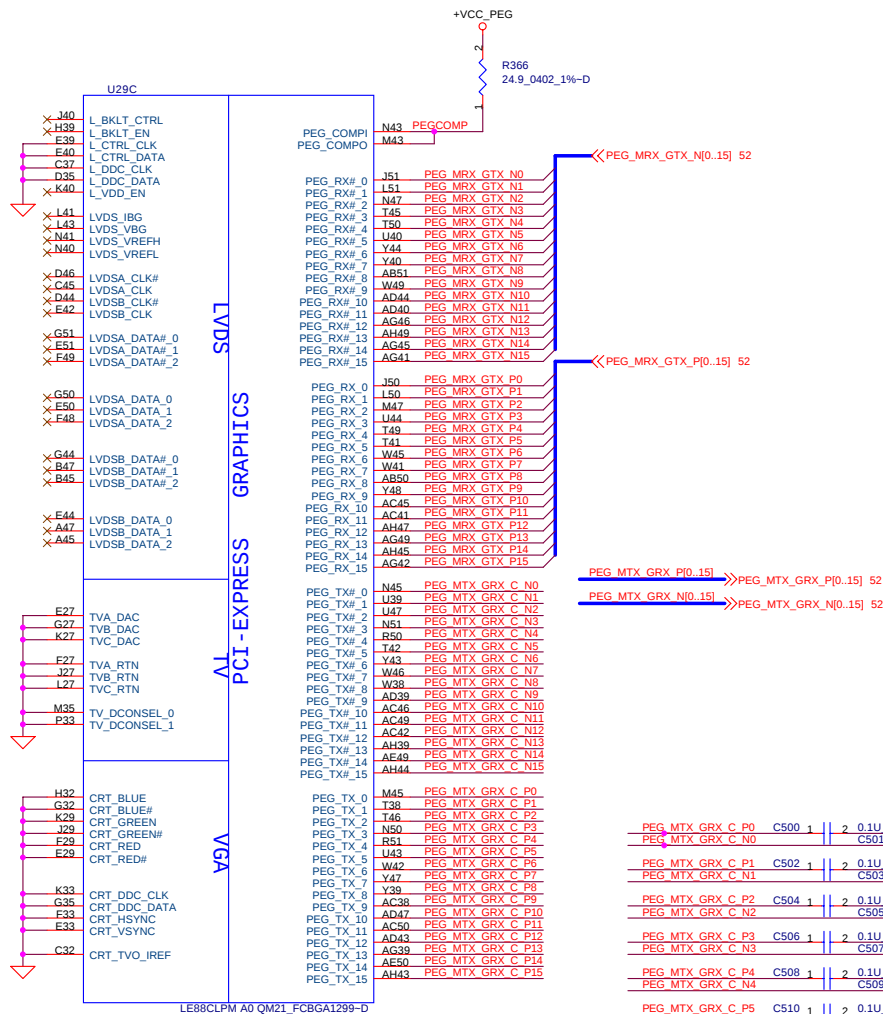


LE88CLPM A0 QM21_FCBGA1299-D

H_A#[3.35] 7

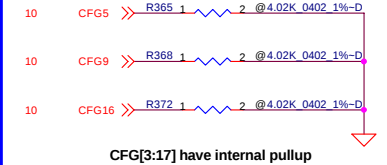
1.8V_SUS



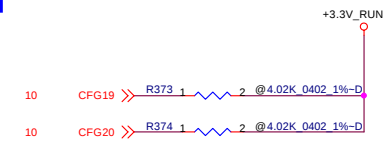


Strap Pin Table

CFG5	DMI X2 Select	Low = DMI x 2 High = DMI x 4 (Default)
CFG9	PCI Express Graphic Lane	Low = Reverse Lane High = Normal Operation (Default)
CFG16	FSB Dynamic ODT	Low=Dynamic ODT Disable High=Dynamic ODT Enable(default)
CFG19	DMI Lane Reversal	Low=Normal (default) High=Lane Reversed
CFG20	SDVO/PCIE Concurrent Operation	Low=Only SDVO or PCIe1 is operational (defaults) High=SDVO and PCIe1 are operating simultaneously via PEG port
SDVO_CTRL_DATA		Low=No SDVO Device Present (default) High=SDVO Device Present



CFG[3:17] have internal pullup



CFG[18:19] have internal pulldown

PEG MTX GRX C P0	C500	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P0
PEG MTX GRX C N0	C501	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N0
PEG MTX GRX C P1	C502	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P1
PEG MTX GRX C N1	C503	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N1
PEG MTX GRX C P2	C504	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P2
PEG MTX GRX C N2	C505	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N2
PEG MTX GRX C P3	C506	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P3
PEG MTX GRX C N3	C507	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N3
PEG MTX GRX C P4	C508	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P4
PEG MTX GRX C N4	C509	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N4
PEG MTX GRX C P5	C510	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P5
PEG MTX GRX C N5	C511	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N5
PEG MTX GRX C P6	C512	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P6
PEG MTX GRX C N6	C513	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N6
PEG MTX GRX C P7	C514	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P7
PEG MTX GRX C N7	C515	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N7
PEG MTX GRX C P8	C516	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P8
PEG MTX GRX C N8	C517	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N8
PEG MTX GRX C P9	C518	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P9
PEG MTX GRX C N9	C519	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N9
PEG MTX GRX C P10	C520	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P10
PEG MTX GRX C N10	C521	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N10
PEG MTX GRX C P11	C522	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P11
PEG MTX GRX C N11	C523	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N11
PEG MTX GRX C P12	C524	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P12
PEG MTX GRX C N12	C525	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N12
PEG MTX GRX C P13	C526	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P13
PEG MTX GRX C N13	C527	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N13
PEG MTX GRX C P14	C528	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P14
PEG MTX GRX C N14	C529	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N14
PEG MTX GRX C P15	C530	1	2	0.1U	0402	10V7K-D	PEG MTX GRX P15
PEG MTX GRX C N15	C531	1	2	0.1U	0402	10V7K-D	PEG MTX GRX N15

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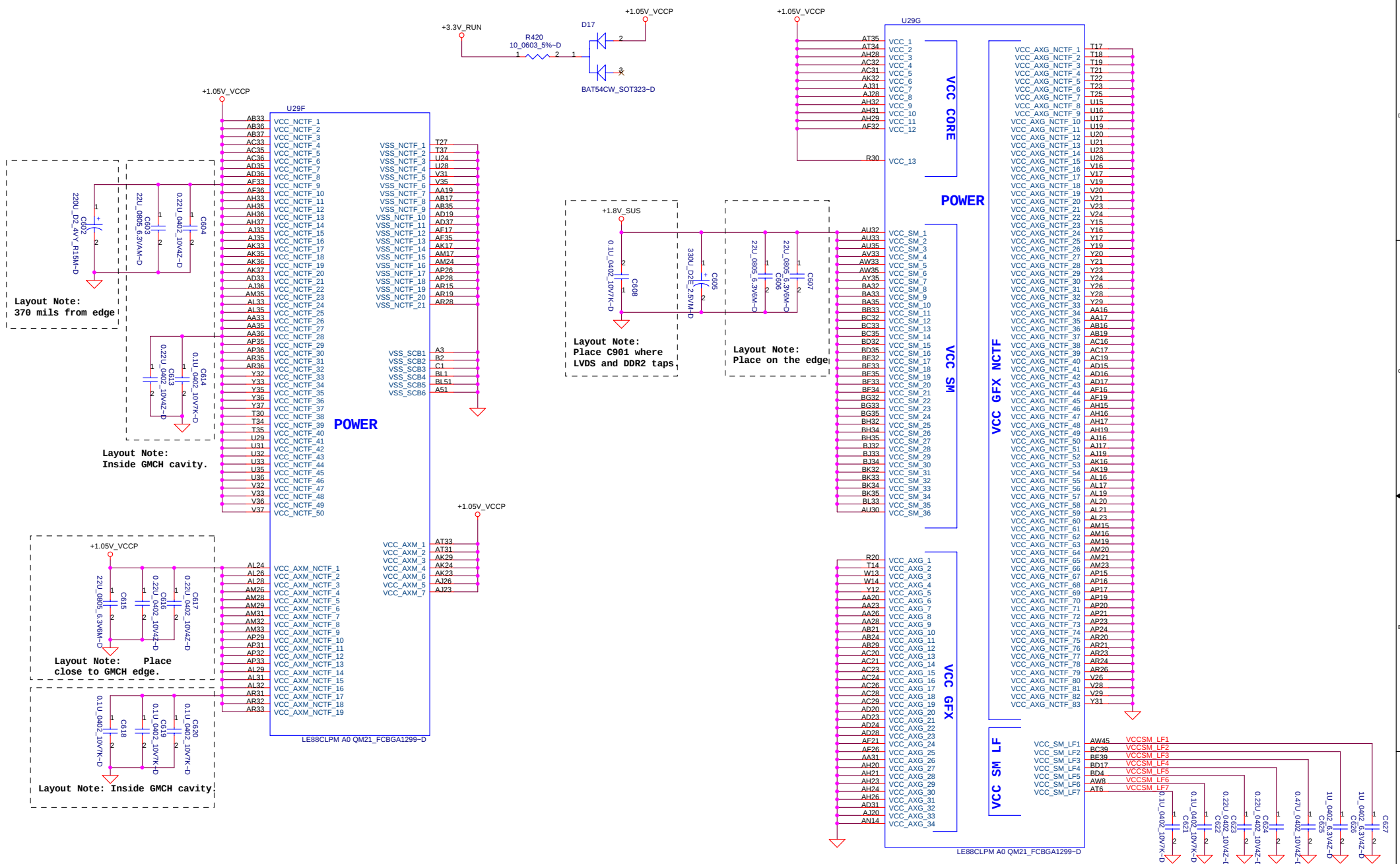
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U29i

A13	VSS_1	VSS_100	AW24
A15	VSS_2	VSS_101	AW29
A17	VSS_3	VSS_102	AW32
A24	VSS_4	VSS_103	AW5
AA21	VSS_104	VSS_104	AW7
AA24	VSS_6	VSS_105	AY10
AA29	VSS_7	VSS_106	AY24
AB20	VSS_8	VSS_107	AY37
AB23	VSS_9	VSS_108	AY42
AB26	VSS_10	VSS_109	AY43
AB28	VSS_11	VSS_110	AY45
AB31	VSS_12	VSS_111	AY47
AC10	VSS_13	VSS_112	AY50
AC13	VSS_14	VSS_113	B10
AC3	VSS_15	VSS_114	B20
AC39	VSS_16	VSS_115	B32
AC43	VSS_17	VSS_116	B39
AC47	VSS_18	VSS_117	B30
AD1	VSS_19	VSS_118	B35
AD21	VSS_20	VSS_119	B38
AD26	VSS_21	VSS_120	B43
AD29	VSS_22	VSS_121	B46
AD3	VSS_23	VSS_122	B5
AD41	VSS_24	VSS_123	B8
AD45	VSS_25	VSS_124	BA1
AD49	VSS_26	VSS_125	BA17
AD5	VSS_27	VSS_126	BA18
AD50	VSS_28	VSS_127	BA2
AD8	VSS_29	VSS_128	BA24
AE10	VSS_30	VSS_129	BB12
AE14	VSS_31	VSS_130	BB25
AE6	VSS_32	VSS_131	BB40
AF20	VSS_33	VSS_132	BB44
AF23	VSS_34	VSS_133	BB49
AF24	VSS_35	VSS_134	BB8
AF31	VSS_36	VSS_135	BC16
AG2	VSS_37	VSS_136	BC29
AG38	VSS_38	VSS_137	BC25
AG43	VSS_39	VSS_138	BC36
AG47	VSS_40	VSS_139	BC40
AG50	VSS_41	VSS_140	BD13
AH3	VSS_42	VSS_141	BD2
AH40	VSS_43	VSS_142	BD28
AH41	VSS_44	VSS_143	BD45
AH7	VSS_45	VSS_144	H4
AH9	VSS_46	VSS_145	BD48
AJ11	VSS_47	VSS_146	BD5
AJ13	VSS_48	VSS_147	BE1
AJ21	VSS_49	VSS_148	BE19
AJ24	VSS_50	VSS_149	BE22
AJ29	VSS_51	VSS_150	BE30
AJ32	VSS_52	VSS_151	BE42
AJ43	VSS_53	VSS_152	BE51
AJ45	VSS_54	VSS_153	BE8
AJ49	VSS_55	VSS_154	BE12
AK20	VSS_56	VSS_155	BF16
AK21	VSS_57	VSS_156	BF36
AK26	VSS_58	VSS_157	BG19
AK28	VSS_59	VSS_158	IG2
AK31	VSS_60	VSS_159	IG24
AK51	VSS_61	VSS_160	IG29
AL1	VSS_62	VSS_161	IG39
AM11	VSS_63	VSS_162	IG48
AM13	VSS_64	VSS_163	L3
AM3	VSS_65	VSS_164	IG51
AM4	VSS_66	VSS_165	L49
AM41	VSS_67	VSS_166	M29
AM45	VSS_68	VSS_167	M44
AN1	VSS_69	VSS_168	M46
AN38	VSS_70	VSS_169	M49
AN39	VSS_71	VSS_170	M5
AN43	VSS_72	VSS_171	M50
AN5	VSS_73	VSS_172	M9
AN7	VSS_74	VSS_173	N11
AP4	VSS_75	VSS_174	N14
AP48	VSS_76	VSS_175	N17
AP50	VSS_77	VSS_176	N29
AR11	VSS_78	VSS_177	N32
AR2	VSS_79	VSS_178	N36
AR39	VSS_80	VSS_179	N39
AR44	VSS_81	VSS_180	N44
AR47	VSS_82	VSS_181	N49
AR7	VSS_83	VSS_182	N7
AT10	VSS_84	VSS_183	P19
AT14	VSS_85	VSS_184	P2
AT41	VSS_86	VSS_185	P23
AT49	VSS_87	VSS_186	P3
AU1	VSS_88	VSS_187	P50
AU23	VSS_89	VSS_188	R49
AU29	VSS_90	VSS_189	T39
AU3	VSS_91	VSS_190	T43
AU36	VSS_92	VSS_191	T47
AU49	VSS_93	VSS_192	U41
AU51	VSS_94	VSS_193	U45
AV39	VSS_95	VSS_194	U50
AV48	VSS_96	VSS_195	V2
AW1	VSS_97	VSS_196	C33
AW12	VSS_98	VSS_197	C36
AW16	VSS_99	VSS_198	C41

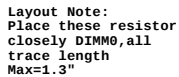
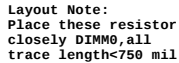
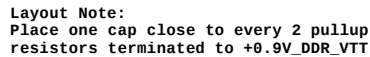
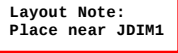
LE88CLPM A0 QM21_FCBGA1299-D

U29j

C46	VSS_199	VSS_287	W11
C50	VSS_200	VSS_288	W39
C7	VSS_201	VSS_289	W43
D13	VSS_202	VSS_290	W47
D24	VSS_203	VSS_291	W5
D3	VSS_204	VSS_292	W7
D32	VSS_205	VSS_293	Y13
D39	VSS_206	VSS_294	Y2
D45	VSS_207	VSS_295	Y41
D49	VSS_208	VSS_296	Y45
E10	VSS_209	VSS_297	Y49
E16	VSS_210	VSS_298	Y5
E24	VSS_211	VSS_299	Y50
E28	VSS_212	VSS_300	Y11
E32	VSS_213	VSS_301	P29
E47	VSS_214	VSS_302	T29
F19	VSS_215	VSS_303	T31
F36	VSS_216	VSS_304	T33
F4	VSS_217	VSS_305	R28
F40	VSS_218		
F50	VSS_219		
G1	VSS_220		
G13	VSS_221	VSS_306	AA32
G16	VSS_222	VSS_307	AB32
G19	VSS_223	VSS_308	AD32
G24	VSS_224	VSS_309	AF28
G28	VSS_225	VSS_310	AF29
G29	VSS_226	VSS_311	AT27
G33	VSS_227	VSS_312	AV25
G42	VSS_228	VSS_313	H50
G45	VSS_229		
G48	VSS_230		
G8	VSS_231		
H24	VSS_232		
H28	VSS_233		
H4	VSS_234		
H45	VSS_235		
J11	VSS_236		
J16	VSS_237		
J2	VSS_238		
J22	VSS_239		
J28	VSS_240		
J33	VSS_241		
J35	VSS_242		
J39	VSS_243		
K12	VSS_245		
K47	VSS_246		
K8	VSS_247		
L1	VSS_248		
L17	VSS_249		
L20	VSS_250		
L24	VSS_251		
L28	VSS_252		
L3	VSS_253		
L33	VSS_254		
L49	VSS_255		
M29	VSS_256		
M44	VSS_257		
M46	VSS_258		
M49	VSS_259		
M5	VSS_260		
M50	VSS_261		
M9	VSS_262		
N11	VSS_263		
N14	VSS_264		
N17	VSS_265		
N29	VSS_266		
N32	VSS_267		
N36	VSS_268		
N39	VSS_269		
N44	VSS_270		
N49	VSS_271		
N7	VSS_272		
P19	VSS_273		
P2	VSS_274		
P23	VSS_275		
P3	VSS_276		
P50	VSS_277		
R49	VSS_278		
T39	VSS_279		
T43	VSS_280		
T47	VSS_281		
U41	VSS_282		
U45	VSS_283		
U50	VSS_284		
V2	VSS_285		
C33	VSS_286		
C36			
C41			

LE88CLPM A0 QM21_FCBGA1299-D



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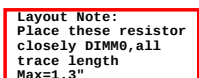
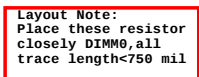
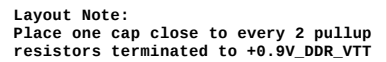
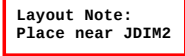
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	LA 3303D	0.4

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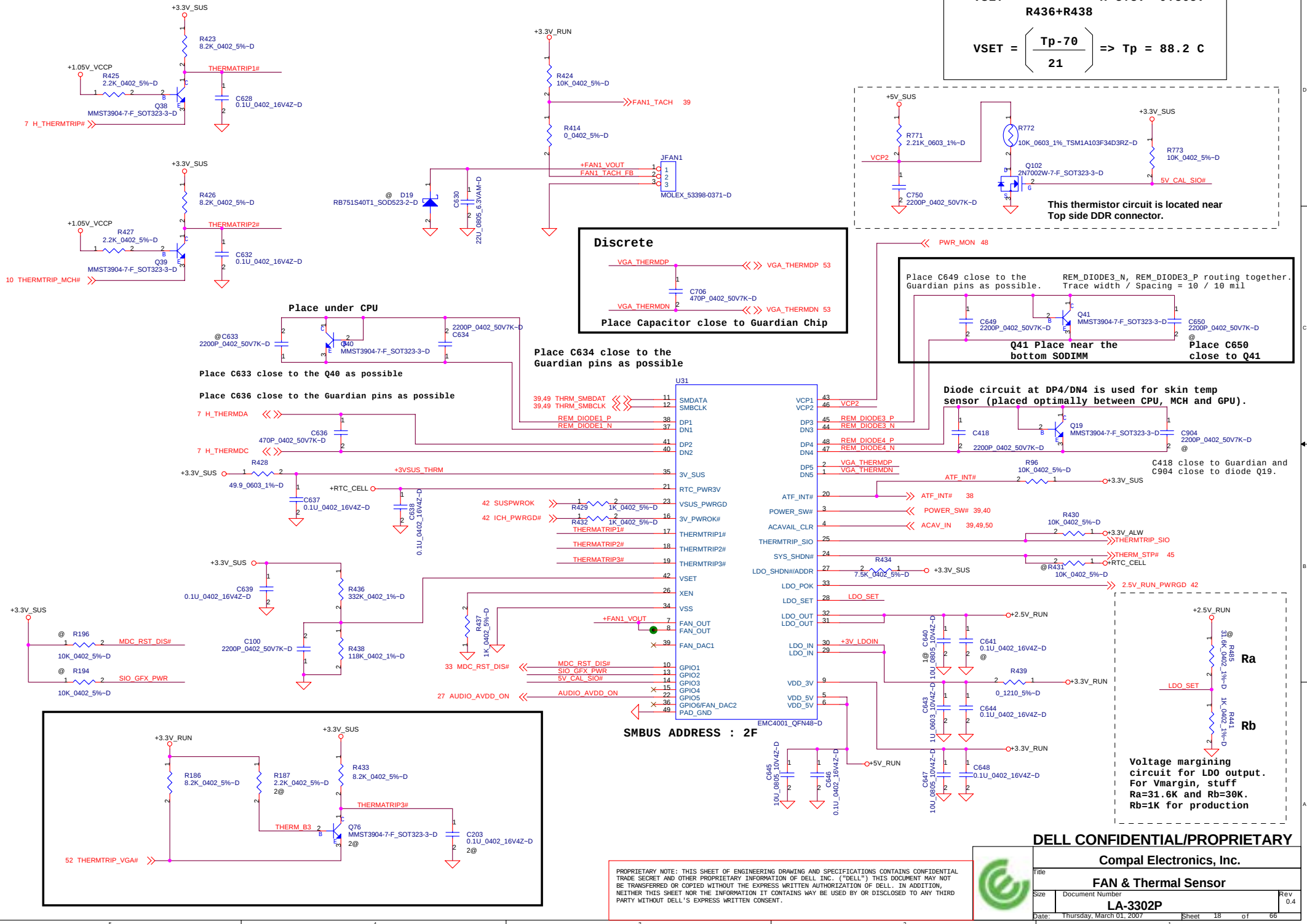


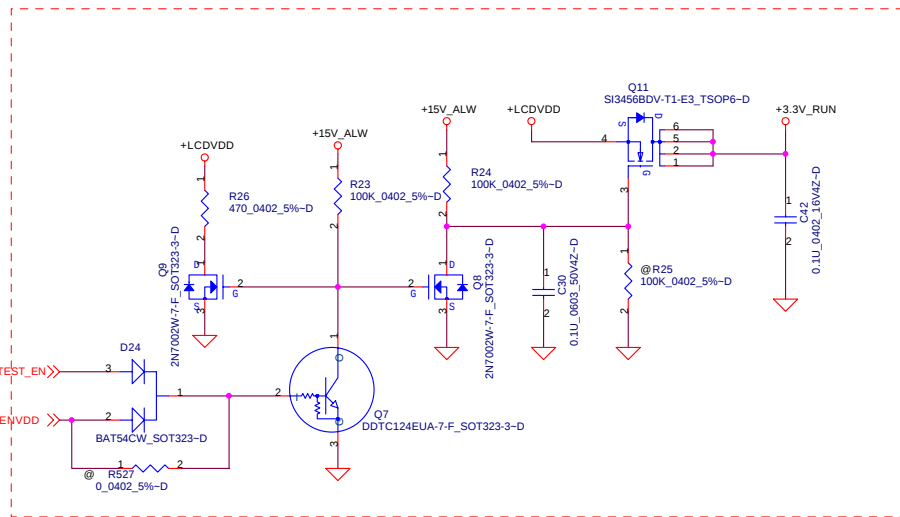
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FAN1 Control and Tachometer

$$VSET = \frac{R438}{R436+R438} \times 3.3V = 0.865V$$

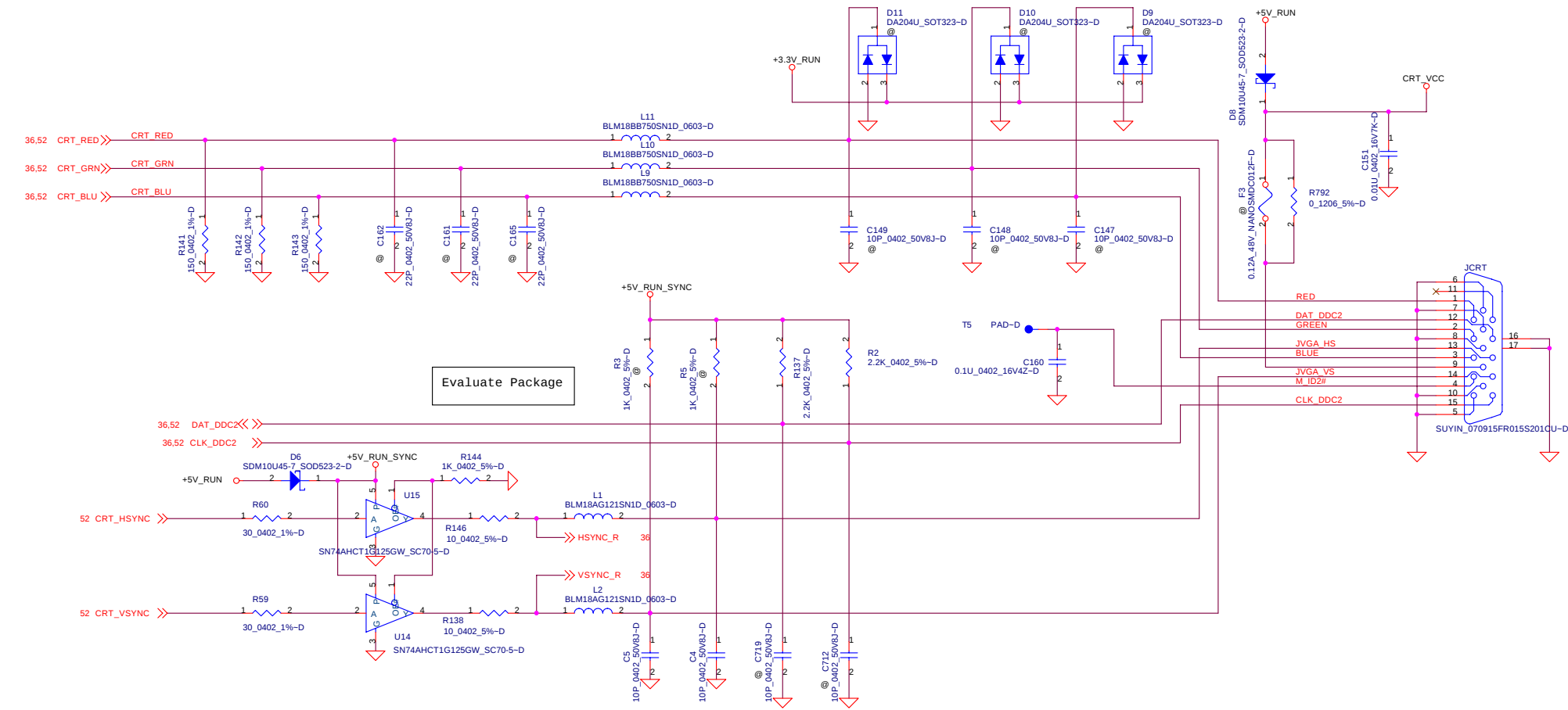
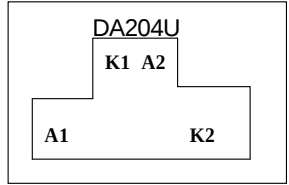
$$VSET = \left(\frac{T_p - 70}{21} \right) \Rightarrow T_p = 88.2 \text{ } ^\circ\text{C}$$





37,39,41,42,51 RUN_ON

FDS4435: P CHANNEL

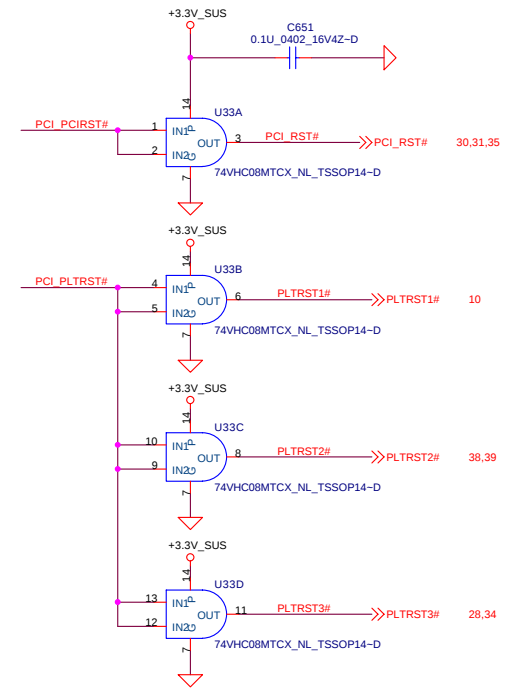
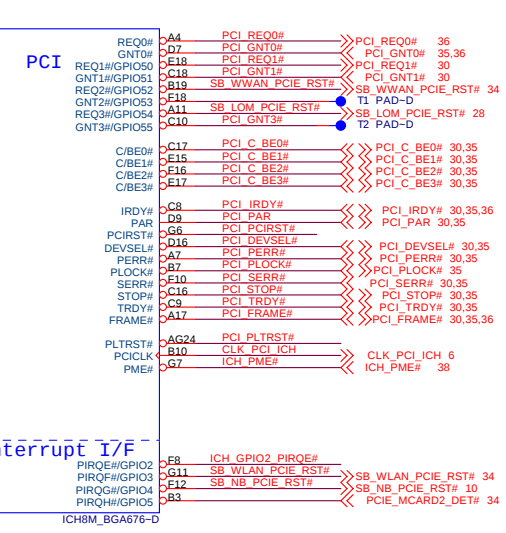
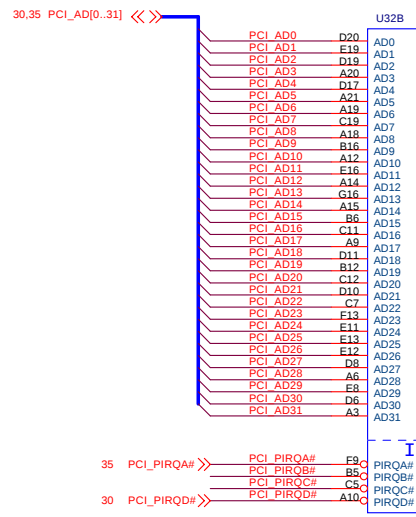
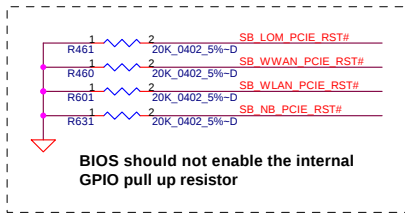
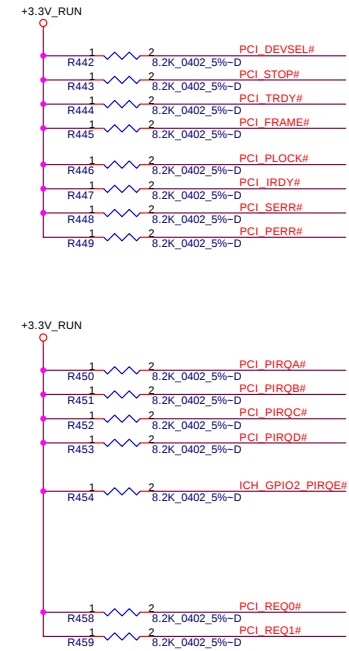


Evaluate Package

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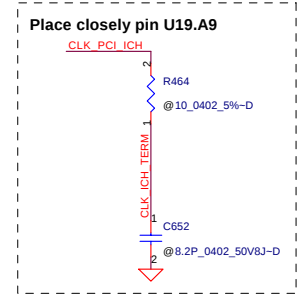


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Compal Electronics, Inc.			
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CRT			
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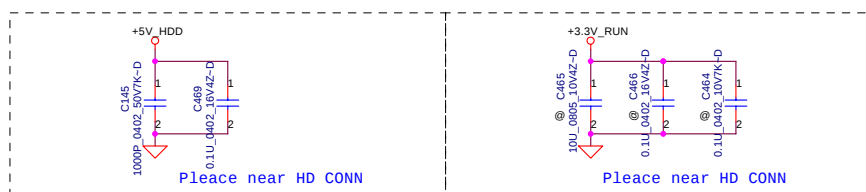
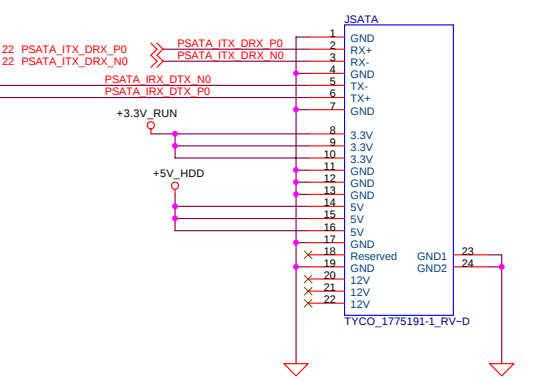
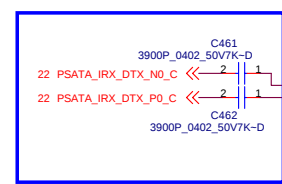
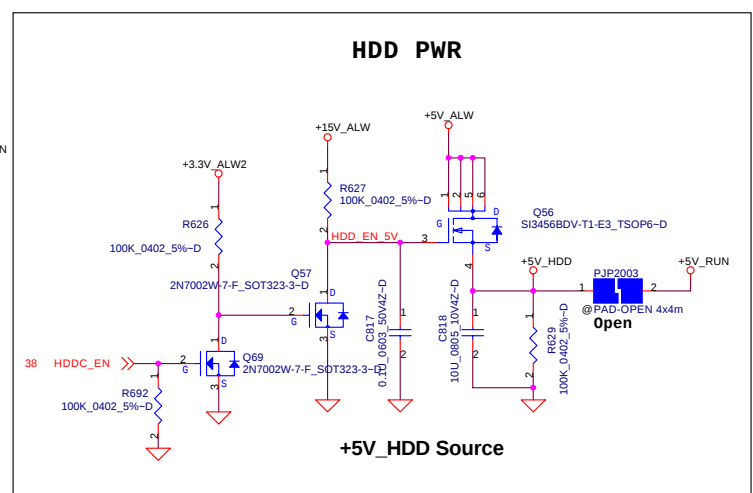
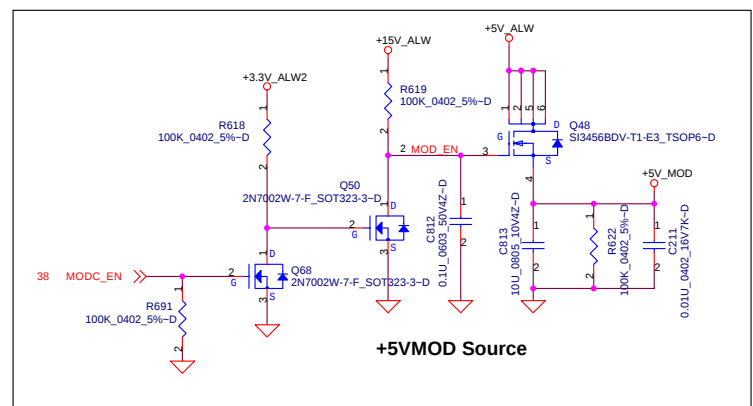
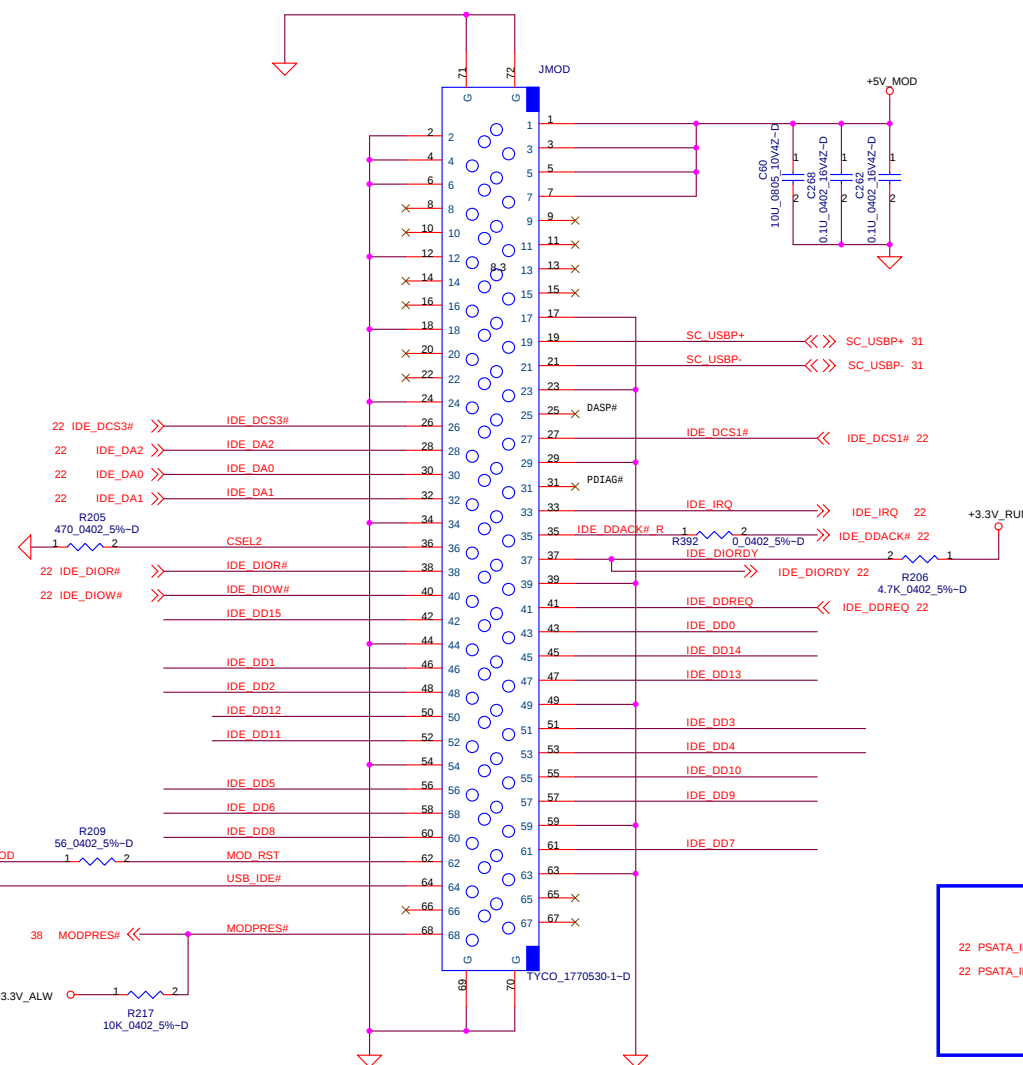
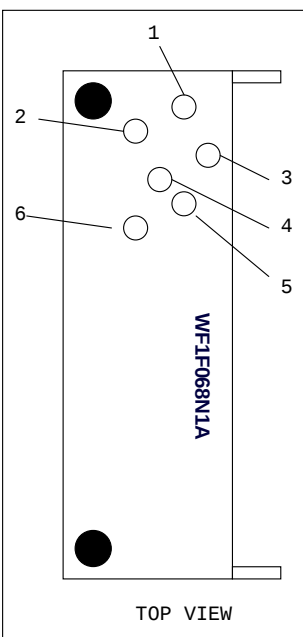


A16 away override strap.	
PCI_GNT3#	Low = A16 swap override enabled. High = Default.

Boot BIOS Strap		
PCI_GNT0#	SPI_CS1#	Boot BIOS Location
0	1	SPI
1	0	PCI
1	1	LPC







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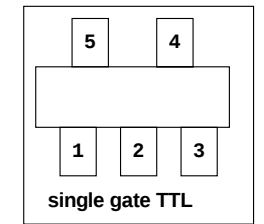
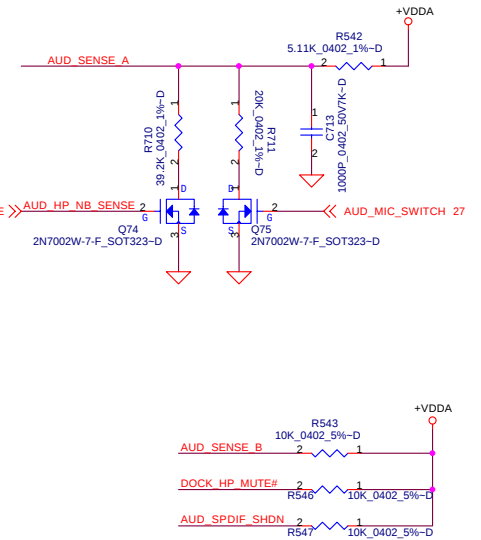
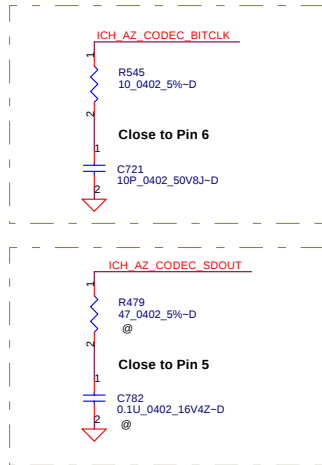
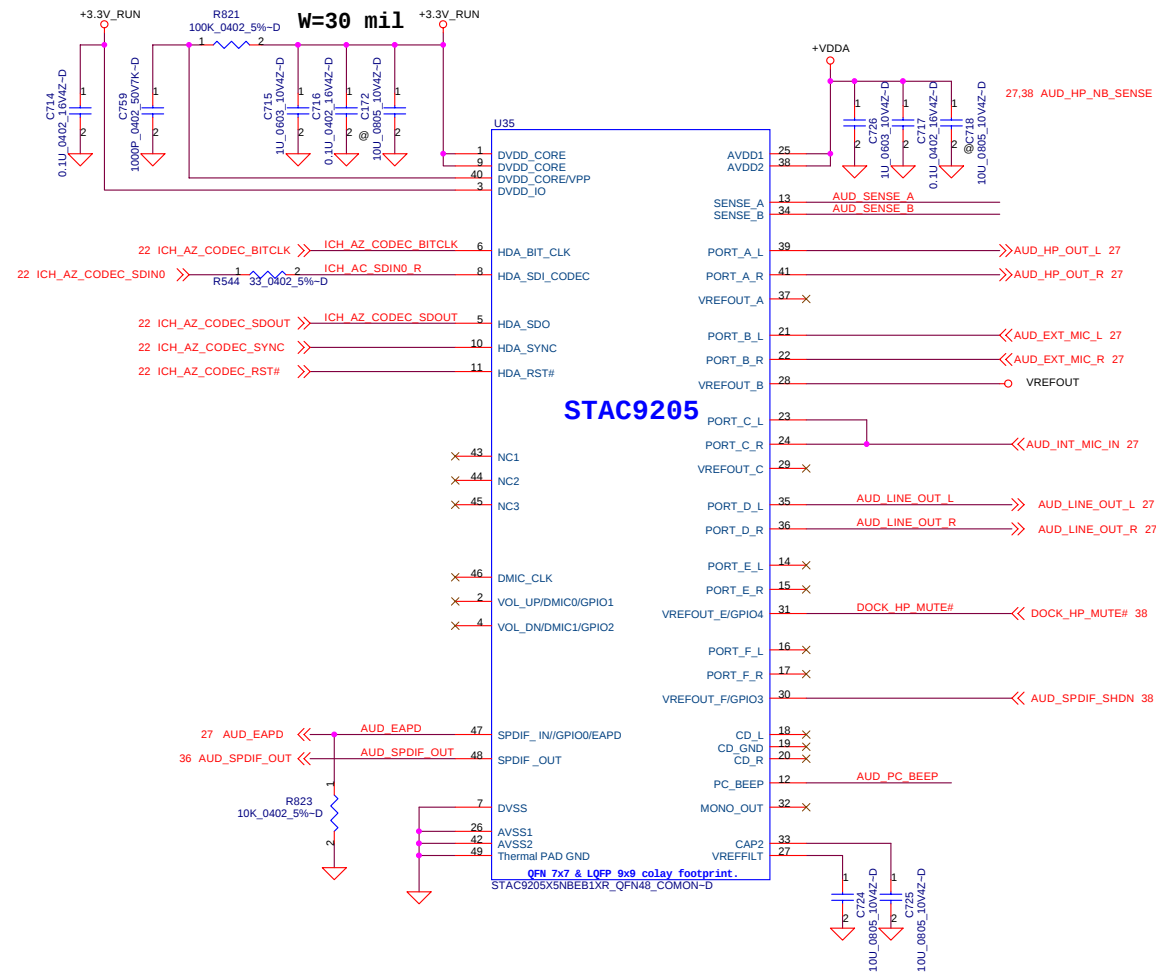
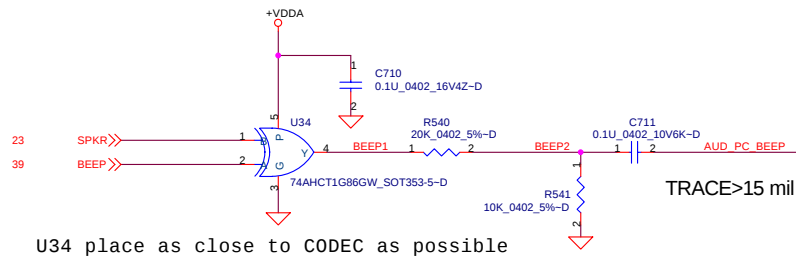
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DVD MODULE

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Azalia (HD) Codec

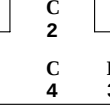
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Layout Notice : Place as close chip as possible.

MMJT9435



R7, R9 are 1/2 W rating

Logic High Voltage must be 0.7V to 2.75V

Place R666 as close to the ASIC as possible. Pad is needed to measure 125MHz clock for debugging

Need to ensure crystal at least 300uW max power drive-level

Layout Notice : No high speed signal should be routed near RDAC or on adjacent layer to RDAC

LOM_CABLE_DETECT goes to an input on a system microcontroller that can poll this signal periodically and can de-assert the LOM_LOW_PWR when LOM_CABLE_DETECT signal is high. Connect to an EC GPIOC defined by the GPIO mapping.

R663 Reserved for BCM5752 as back-up solution

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Layout Notice : 1.2V filter. Place as close chip as possible.

	NV_STRAP1	NV_STRAP0	SO	SI	CS#	SCLK
Auto-Sense Mode (Default)	0	0	0	0	0	0
Atmel AT458CM021B	0	0	1	0	1	1
ST M45PE20	0	1	1	1	0	1

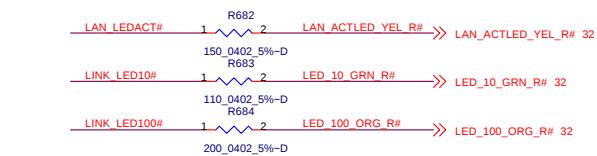
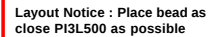
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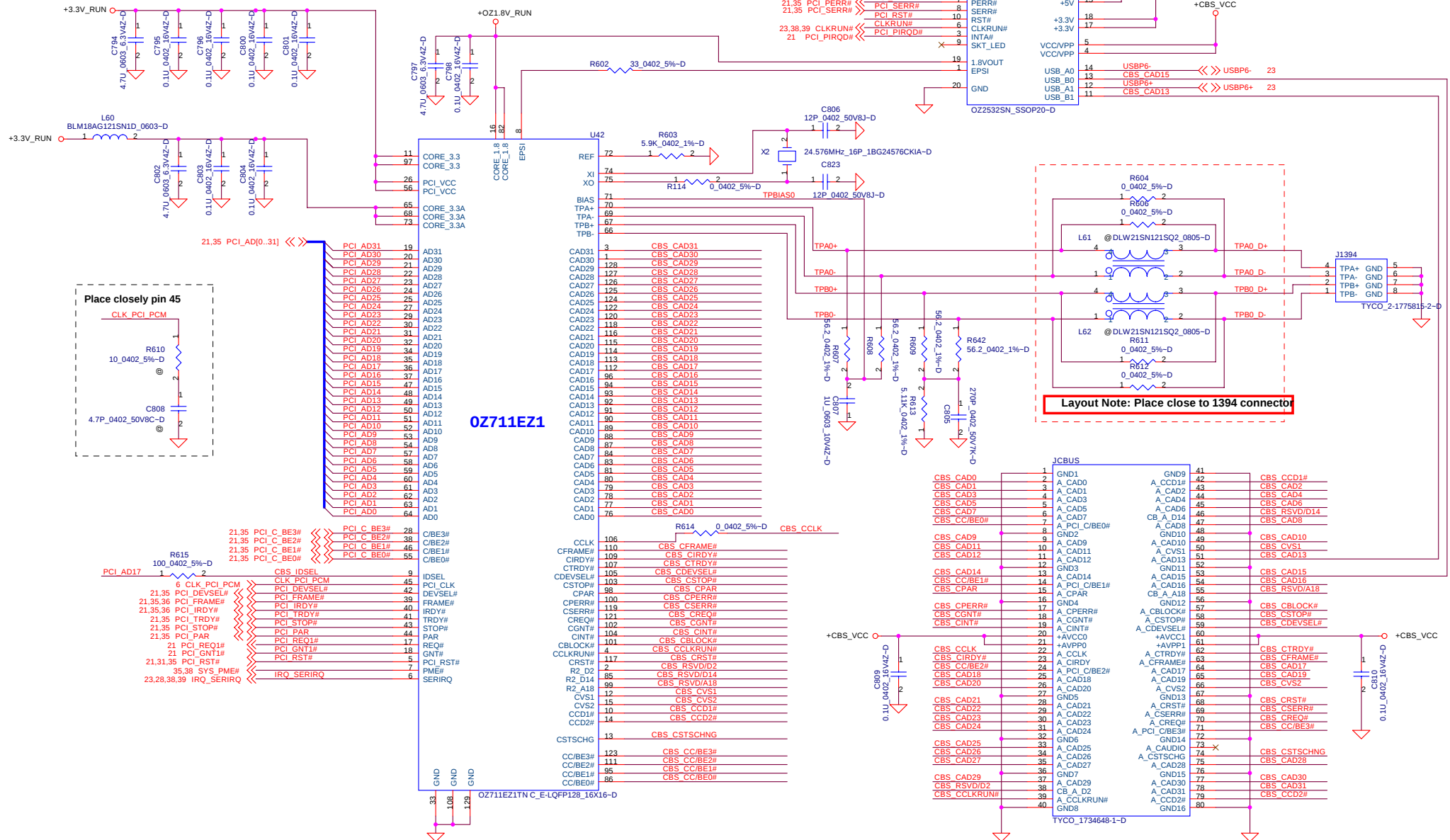
Compal Electronics, Inc.

BCM5755M

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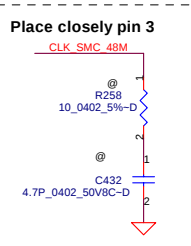
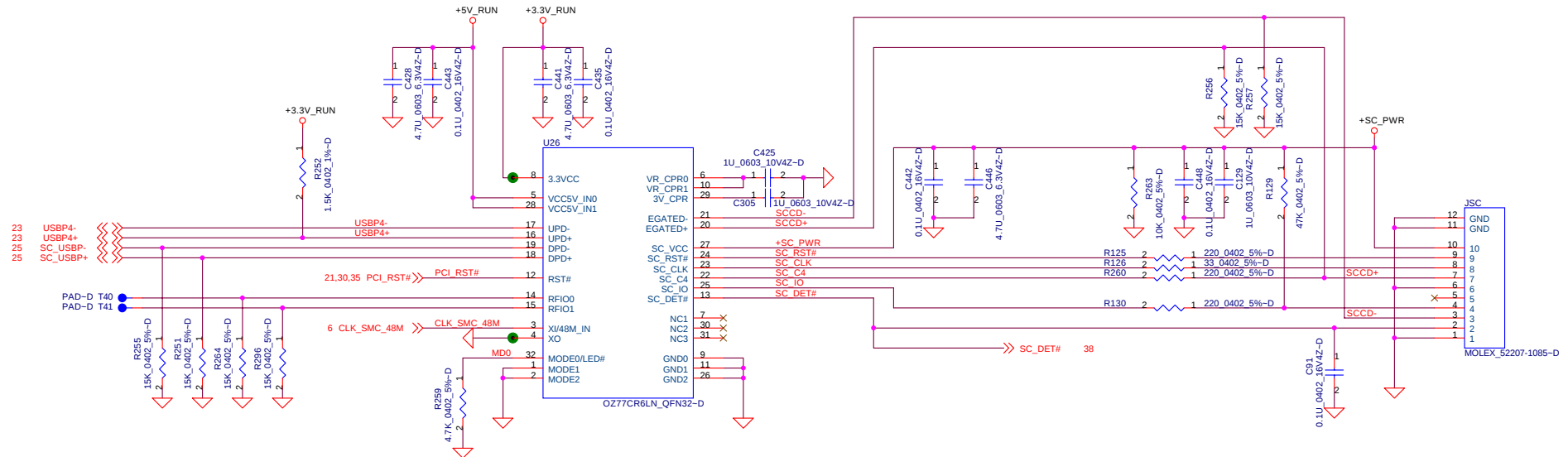


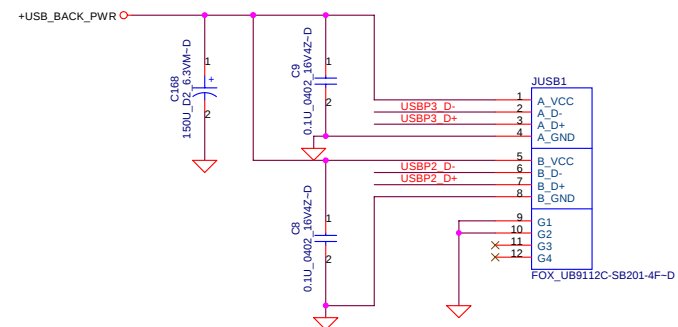
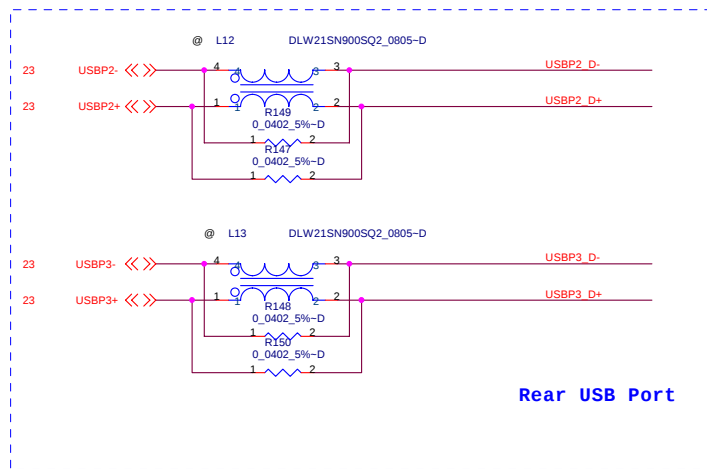
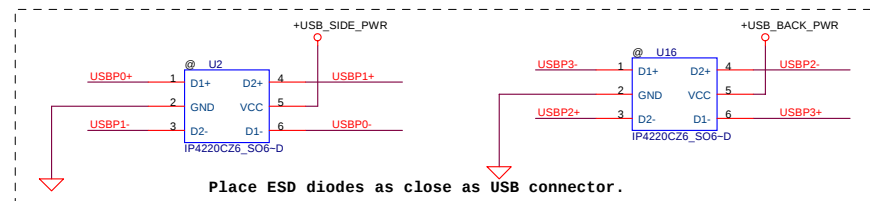
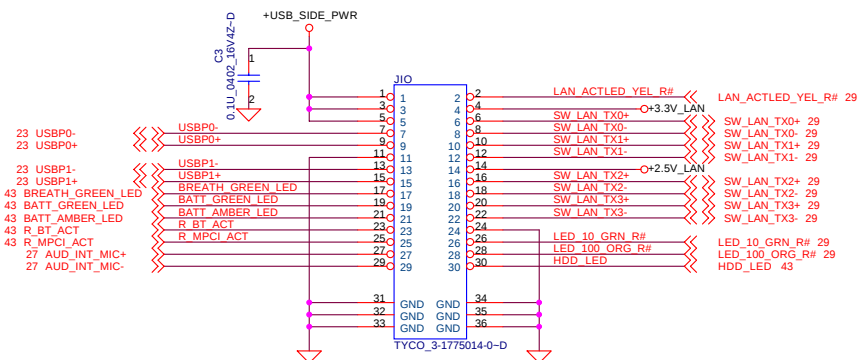
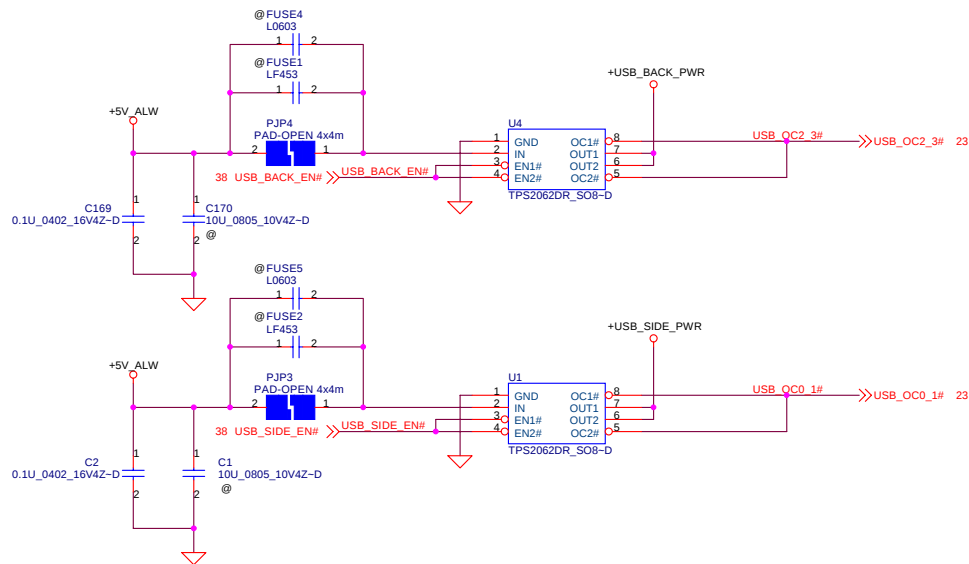


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USB SMARTCARD READER.
TYPE A (5V), B (3V), AB (5V/3V)
& USB SMARTCARDS ARE SUPPORTED.





Rear USB Ports

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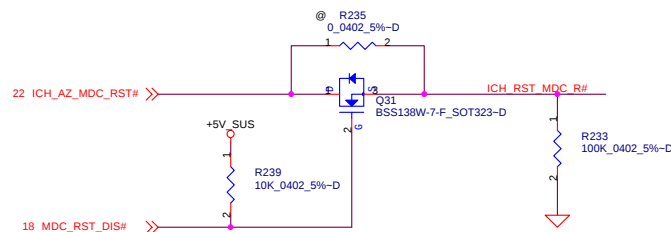
USB 2.0 Port

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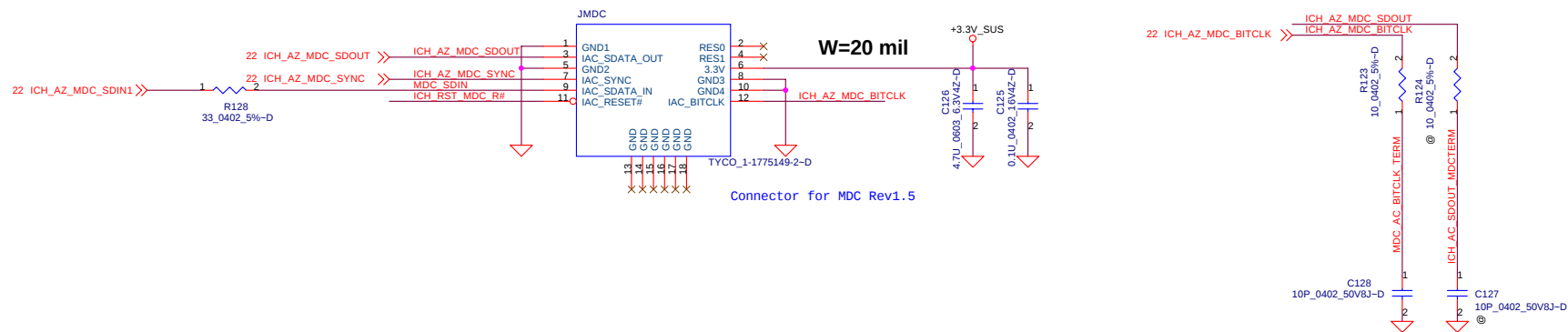


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New MDC connector.

1	GND	RES	2
3	IAC_SDATA0	RES	4
5	GND	3.3V	6
7	IAC_SYNC	GND	8
9	IAC_SDATAIN	GND	10
11	IAC_RESET#	IAC_BITCLK	12



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BT PORT and MDC

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2V
0.4

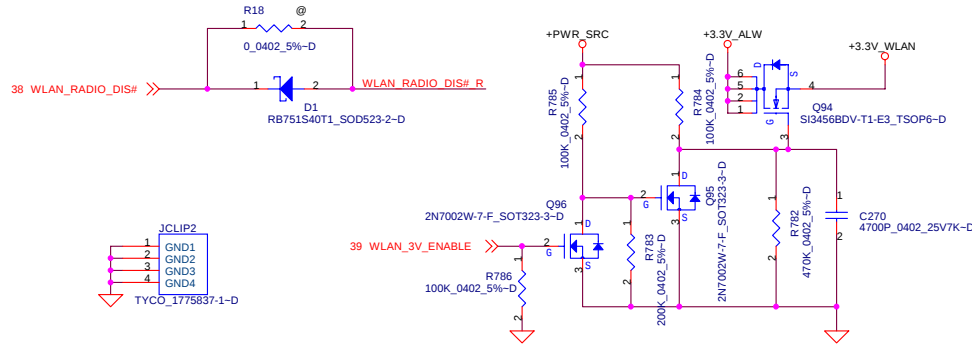
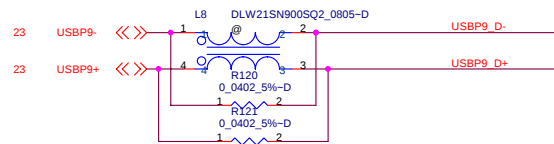
Date: Thursday, March 01, 2007

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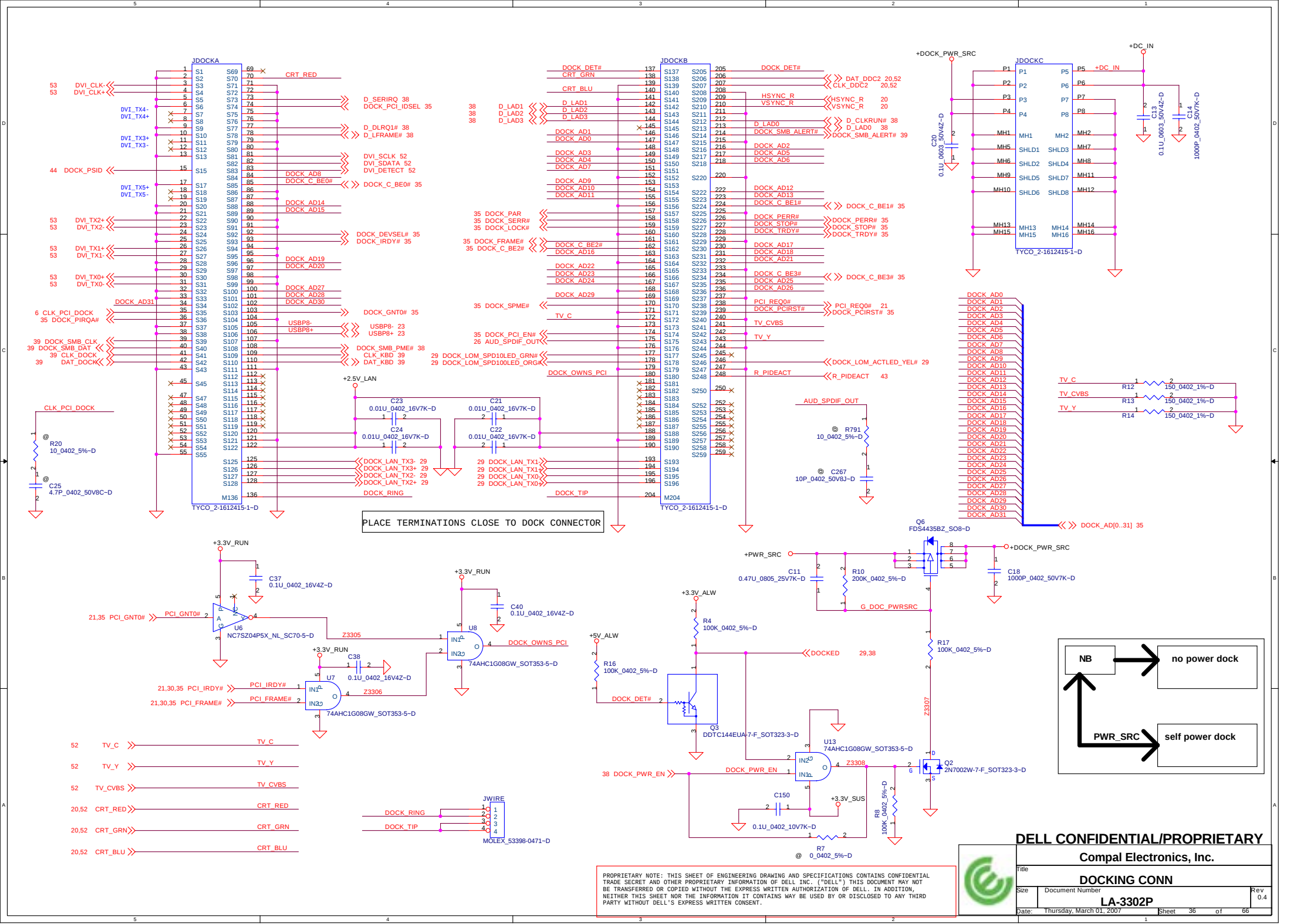


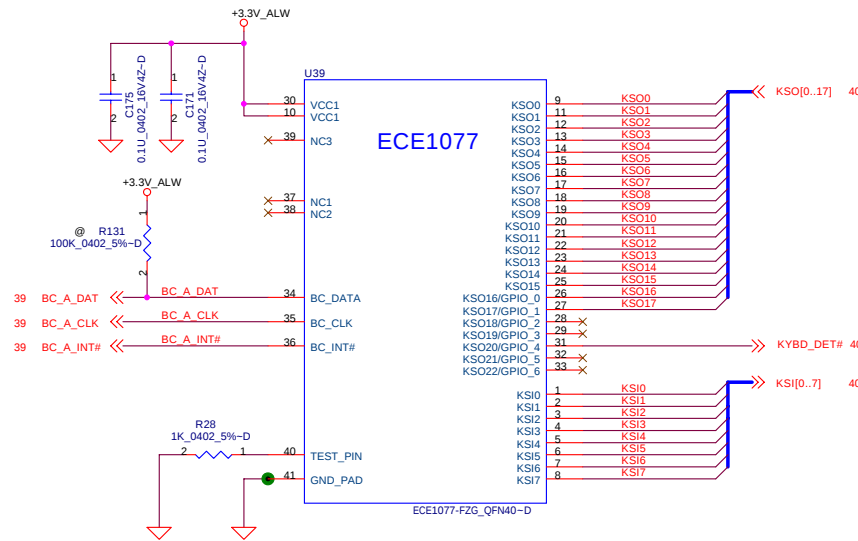
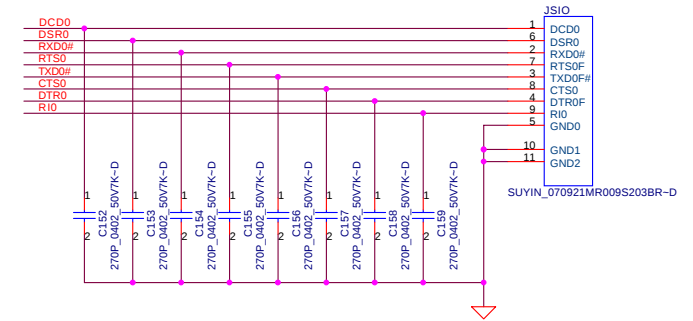
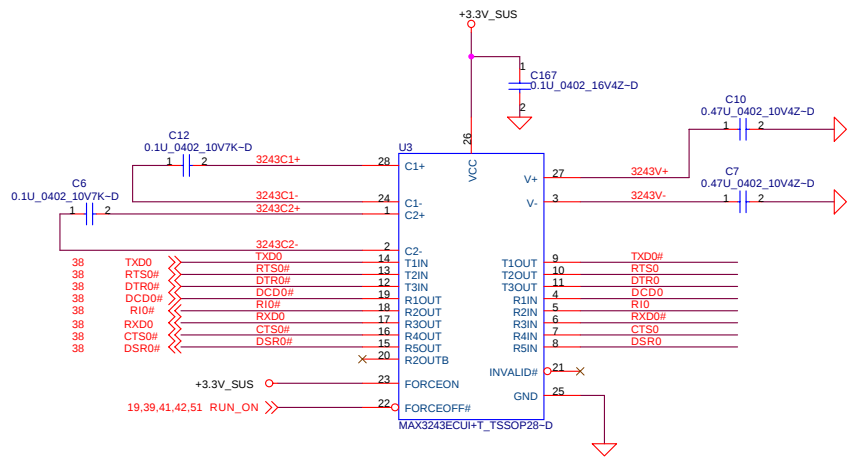


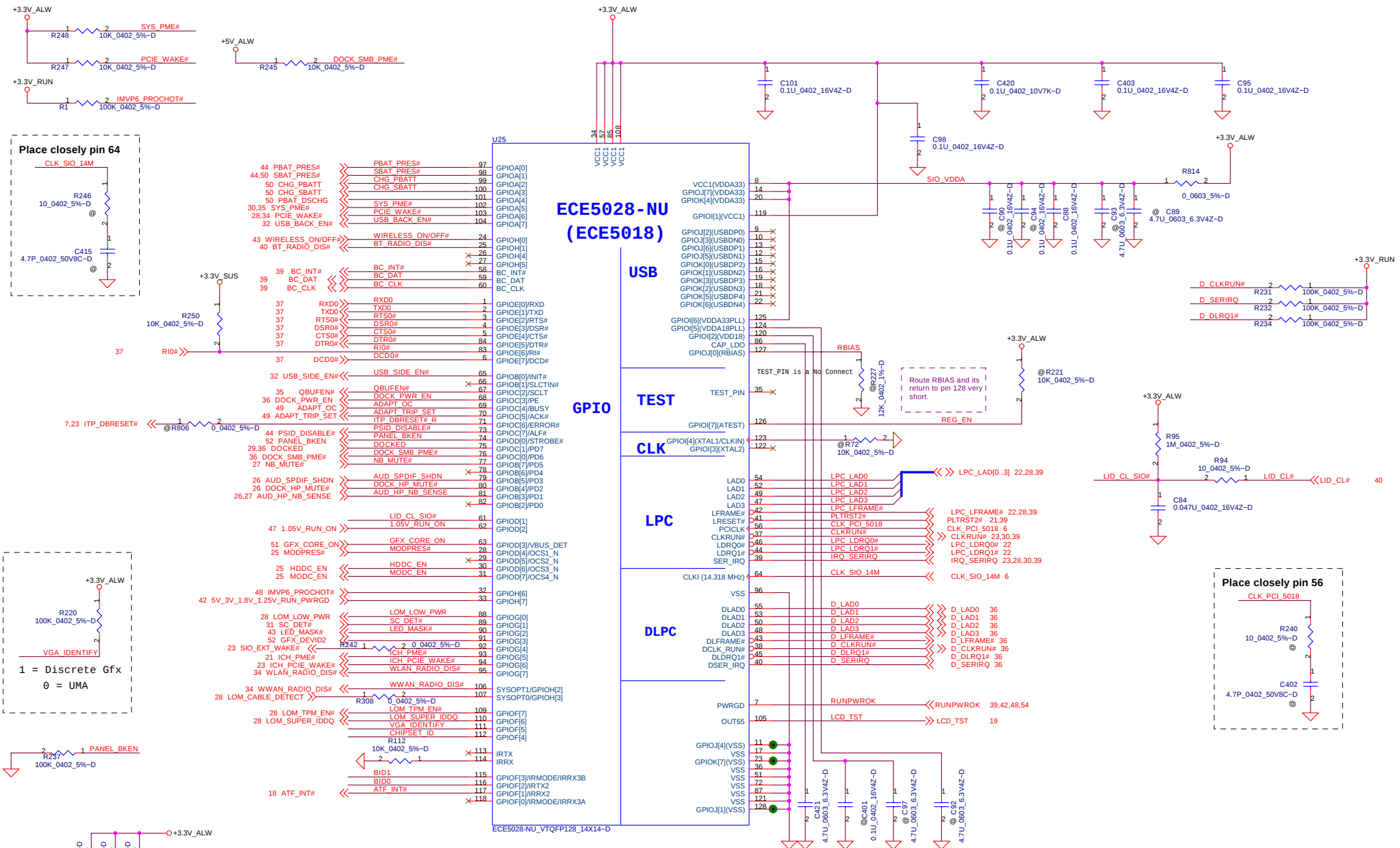
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DOCKING BUFFER		
Size	Document Number	Rev
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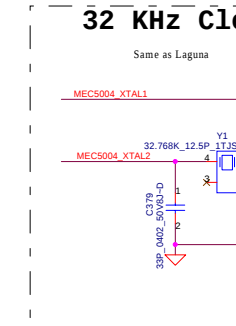
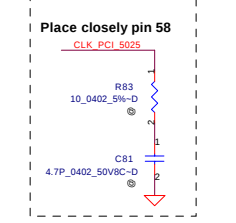
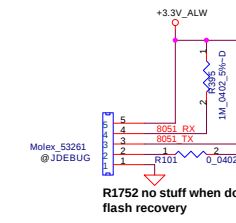
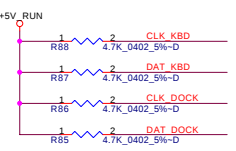
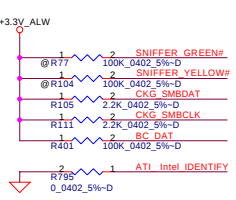
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X00	0	0
X01	0	1
X02	1	0
X03	1	1

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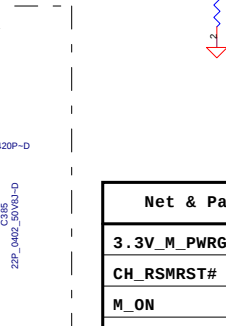
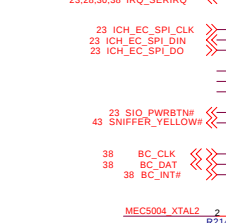
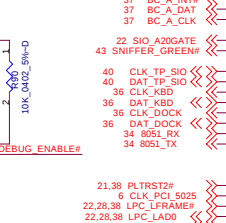
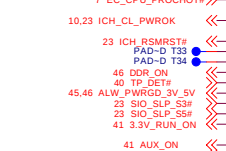
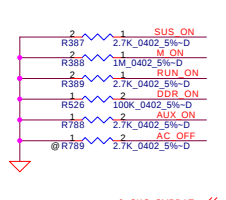


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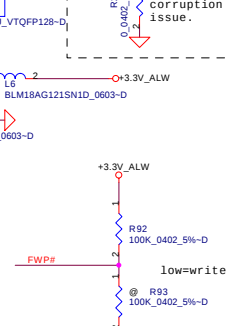
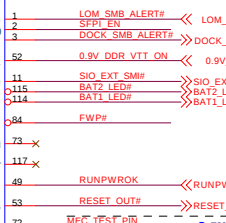
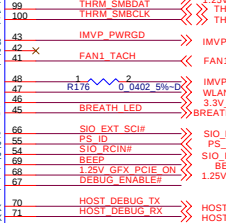
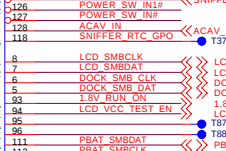
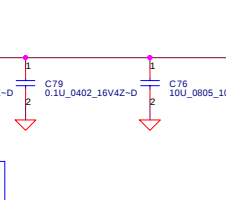
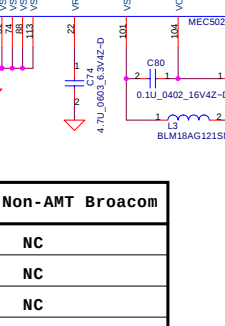
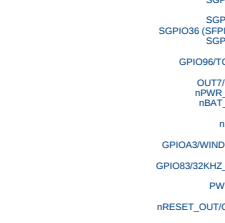
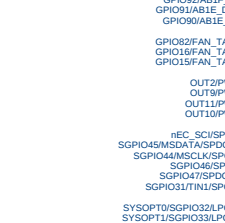
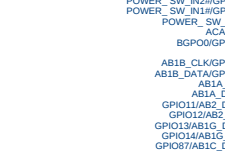
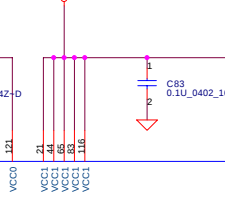
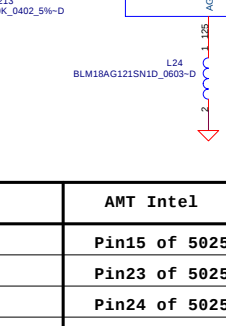
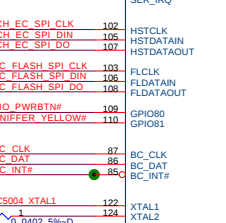
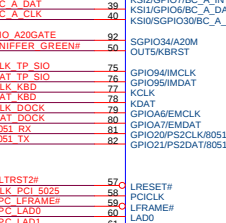
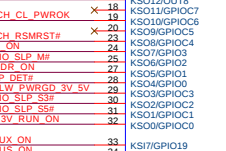
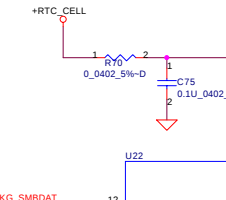
Compal Electronics, Inc.		
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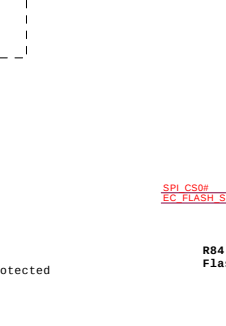
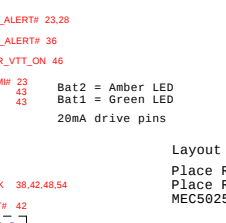
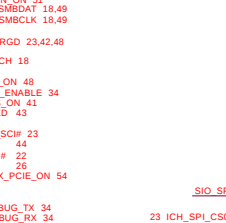
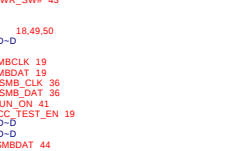
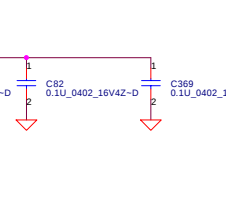
hexainf@hotmail.com
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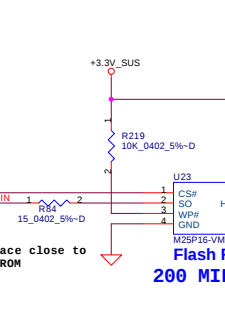
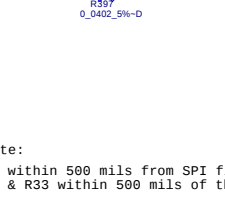
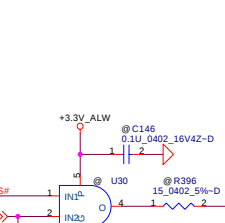
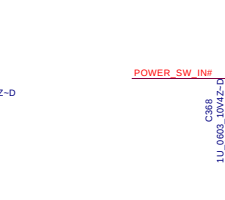
Net & Part	AMT Intel	Non-AMT Broacom
3.3V_M_PWRGD	Pin15 of 5025	NC
CH_RSMRST#	Pin23 of 5025	NC
M_ON	Pin24 of 5025	NC
SIO_SLP_M#	Pin25 of 5025	NC
1.05V_1.25V_M_PWRGD	Pin37 of 5025	NC
R238	Pin24 of 5025	NC
LOM_SUPER_IDDQ	NC	Refer to UMA
LOM_LOW_PWR	NC	Refer to UMA
LOM_CABLE_DETECT	NC	Refer to UMA



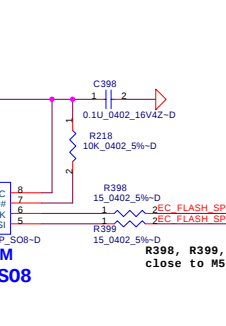
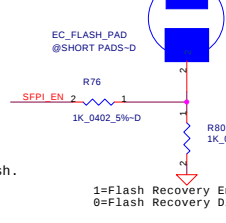
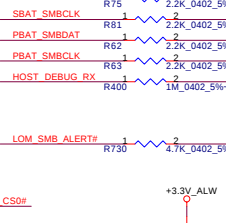
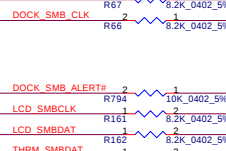
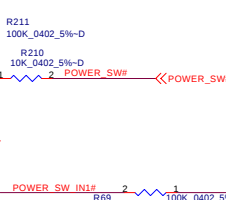
Flash write protect bottom 4K of internal bootblock flash



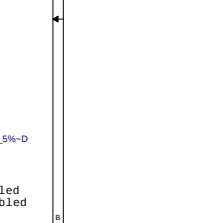
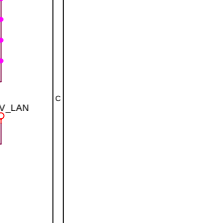
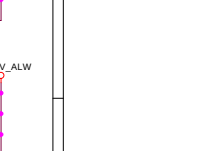
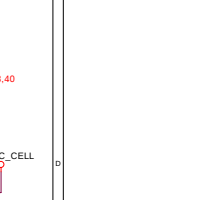
Flash write protect bottom 4K of internal bootblock flash



Flash write protect bottom 4K of internal bootblock flash



Flash write protect bottom 4K of internal bootblock flash



Flash write protect bottom 4K of internal bootblock flash

Layout Note:
Place R84 within 500 mils from SPI flash.
Place R32 & R33 within 500 mils of the MEC5025.

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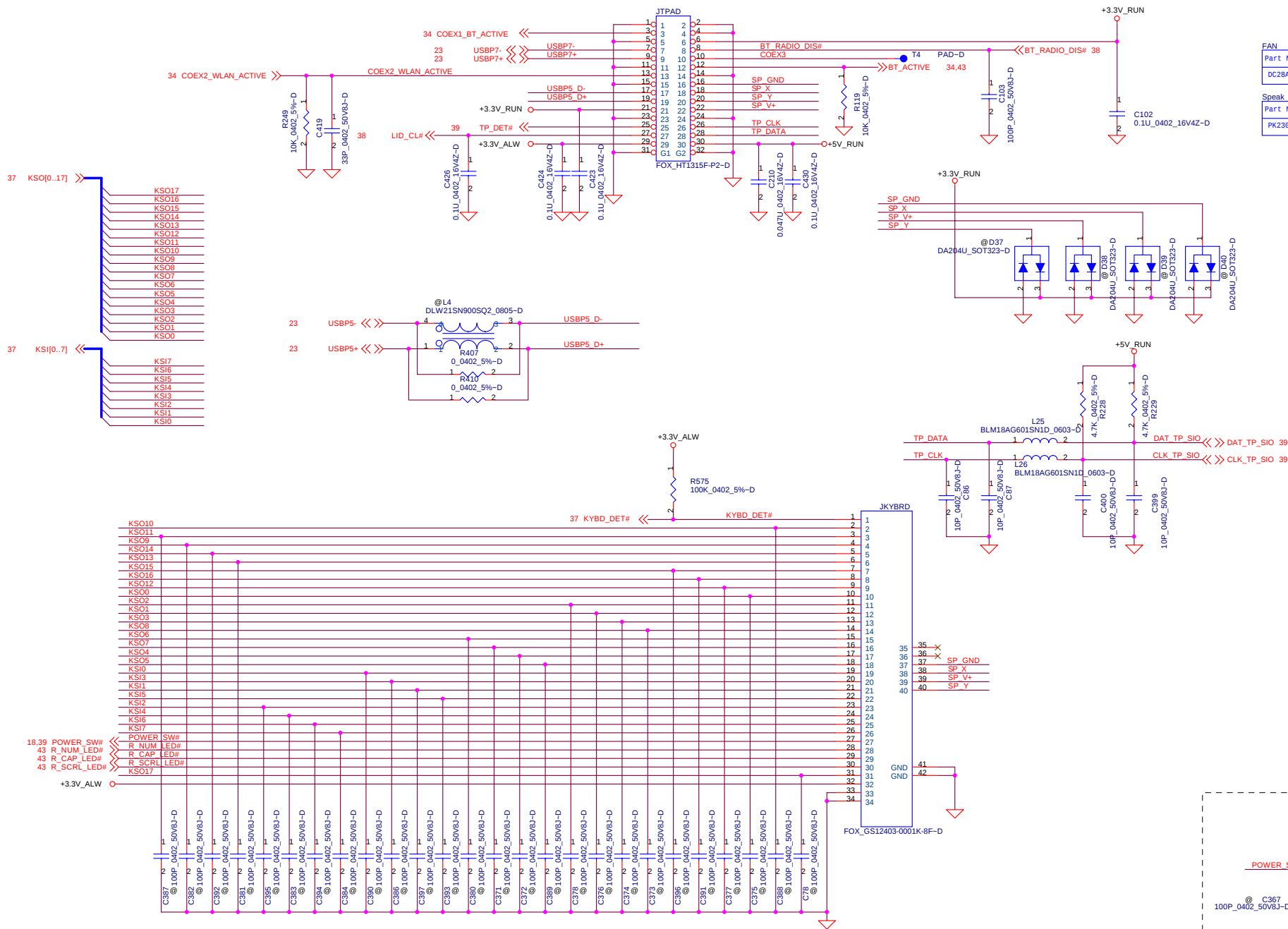
EMC5025

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Touch PAD



Part Number	Description
DC28A988880	FAN SET DAQ20 DC5V AB7485HB-HB3 ADDA

Part Number	Description
PK230803Q0L	SPK PACK ZJX 2.0W 4 OHM FG

Part Number	Description
SP070807V0L	S SOCKET TYCO 1778551-1 18P H5.9 SMART

Part Number	Description
DC0808081Q0L	PCMCIA TYCO 1759896-1

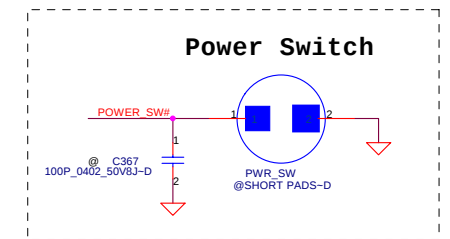
Part Number	Description
DC820808CS0L	H-CONN SET ZGX MB-MDC

Part Number	Description
DC82080848L	H-CONN SET ZJX MB-B/T-TP-FP

Part Number	Description
DC8208083Y0L	H-CONN SET ZJX MB-LCD 14 WXGA+(-1ch)

Part Number	Description
DC82080878L	H-CONN SET ZJX MB-LCD 14 WXGA+(-2ch)

Part Number	Description
GC28323MX08	BATT CR2832 3V 220MAH MAXELL

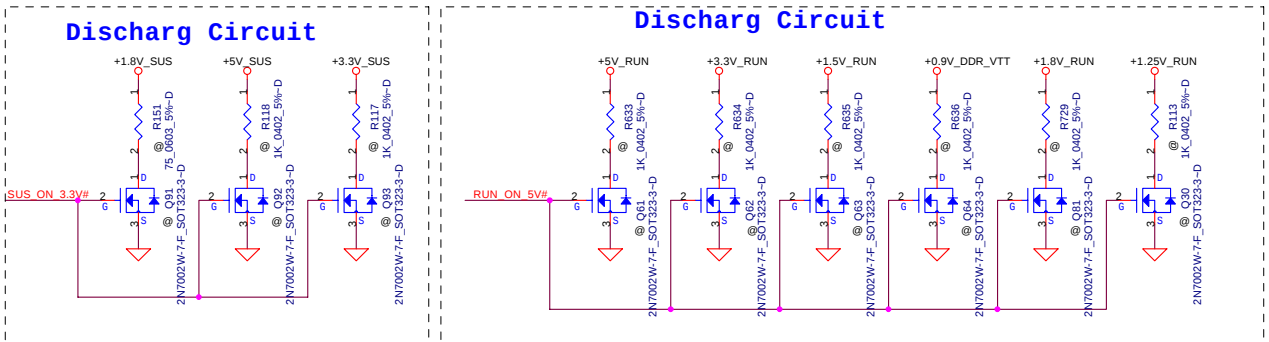
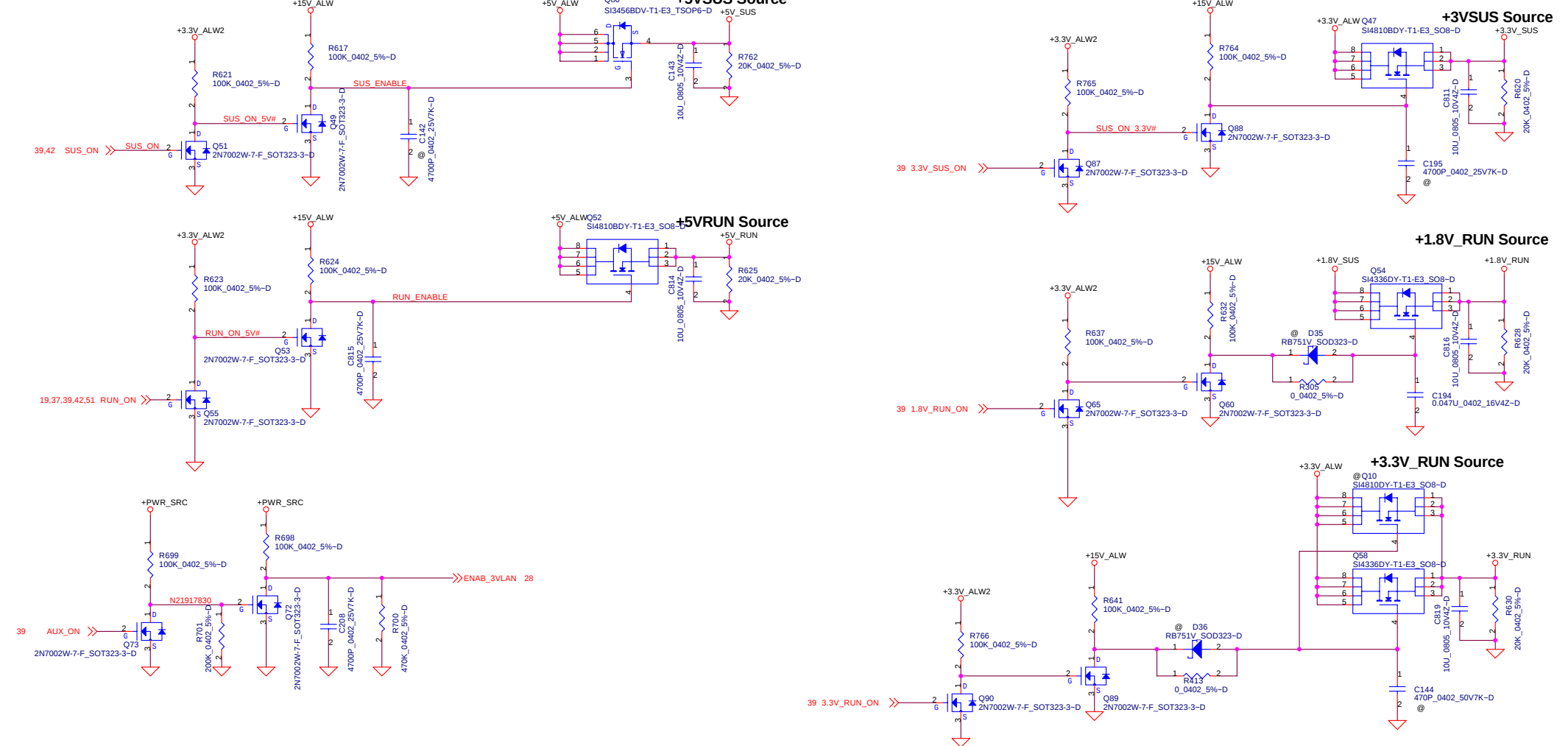


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DC/DC Interface



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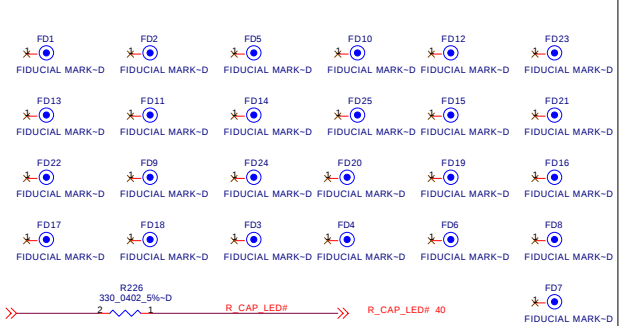
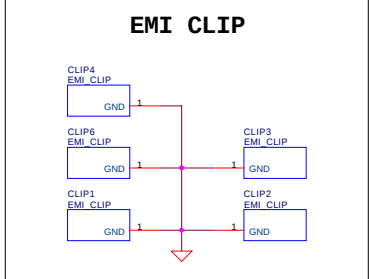
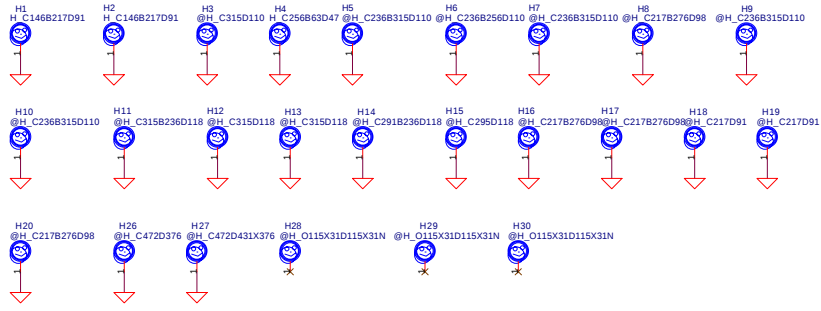
POWER CONTROL

LA-3302P

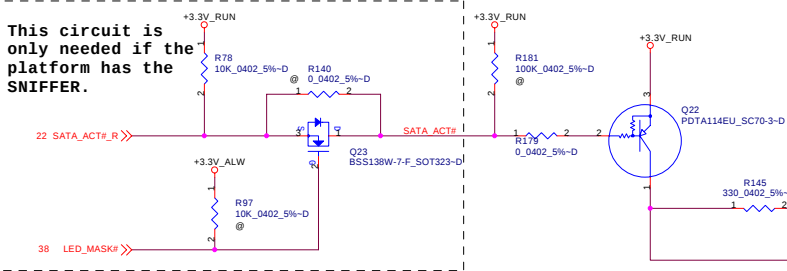
Thursday, March 01, 2007

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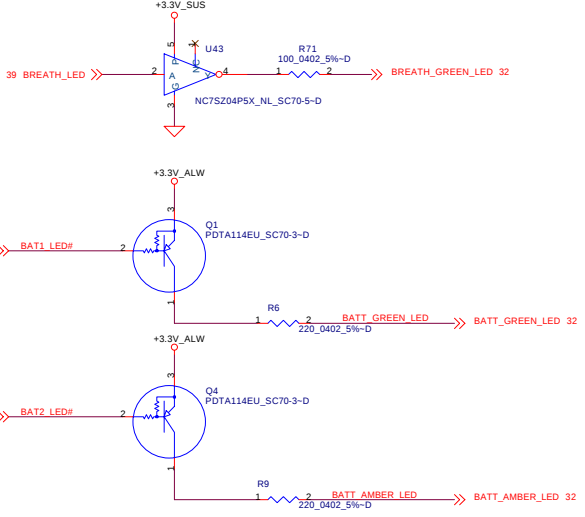
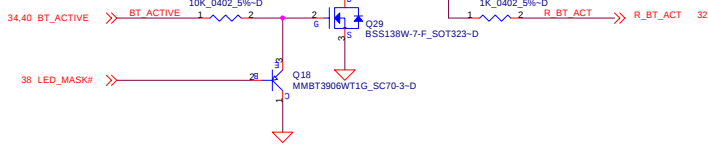
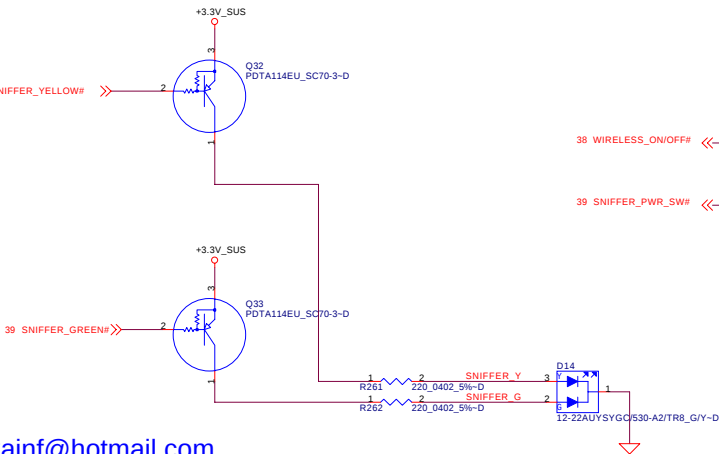
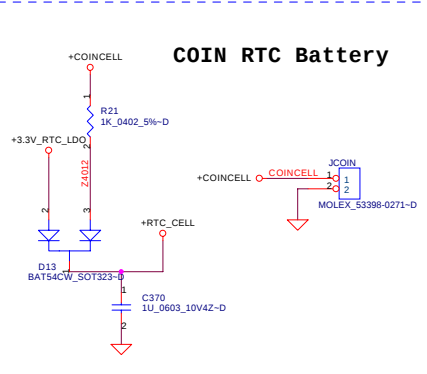
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This circuit is only needed if the platform has the SNIFFER.



COIN RTC Battery



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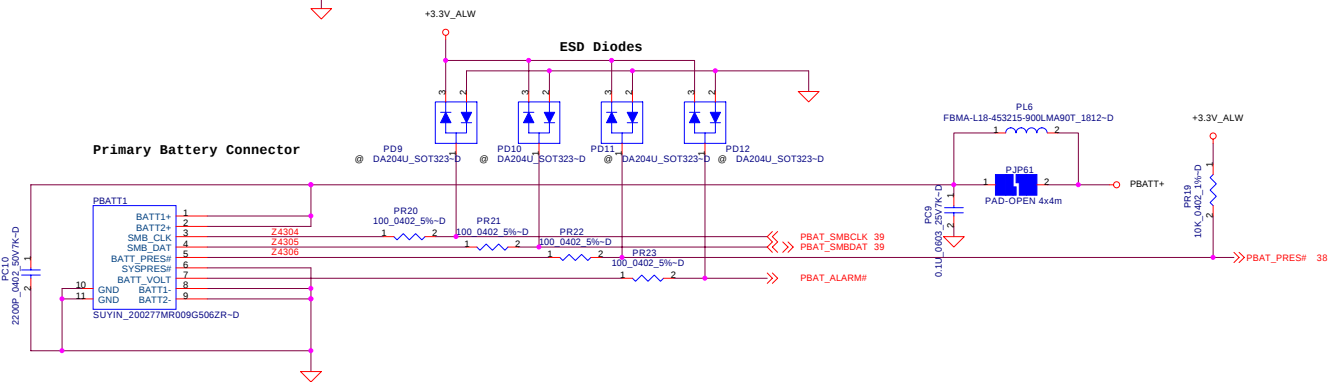
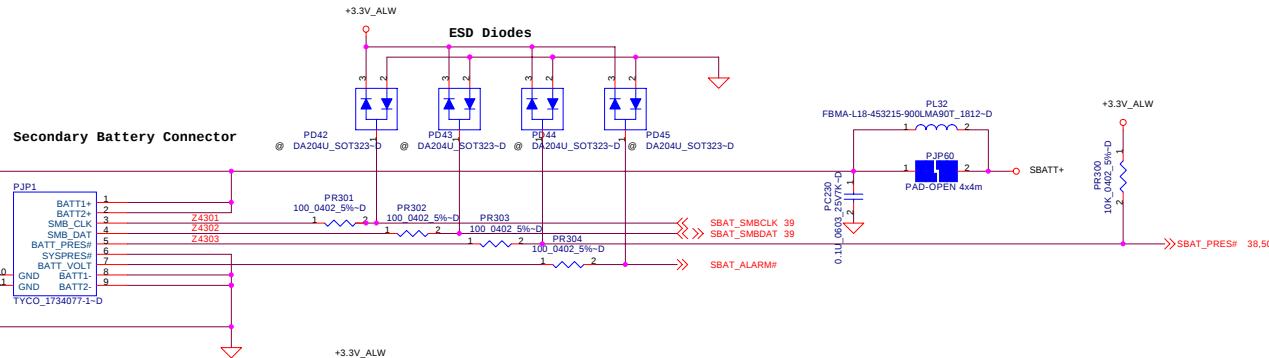
PAD and Standoff

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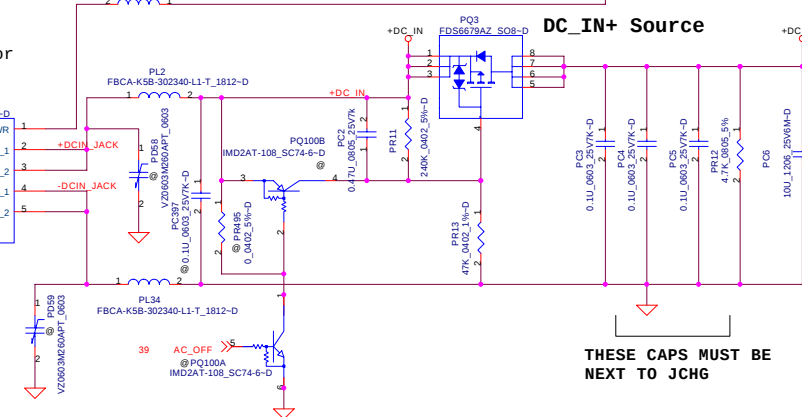
hexainf@hotmail.com
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GPIO Input from EC

PL1 BLM188D102SNID_0603-D



THESE CAPS MUST BE
NEXT TO JCHG

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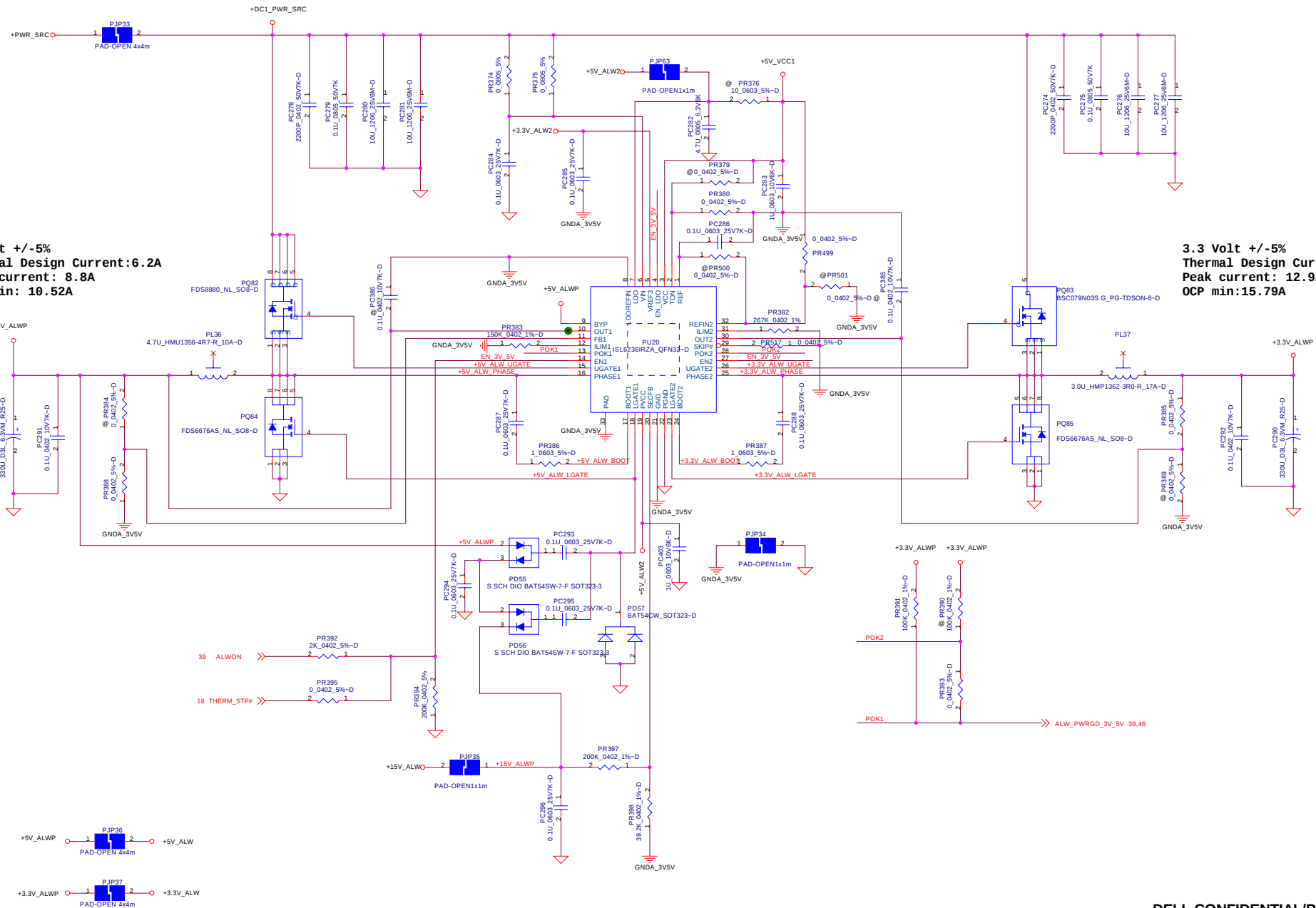
Compal Electronics, Inc.

+DCIN

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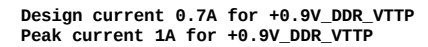
3.3 Volt +/-5%
Thermal Design Current:9.0A
Peak current: 12.9A
OCP min:15.79A



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PR193, PD20 are only used with the second-source MAX8632.



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+1.8VSUSP/ +0.9V_DDR_VT

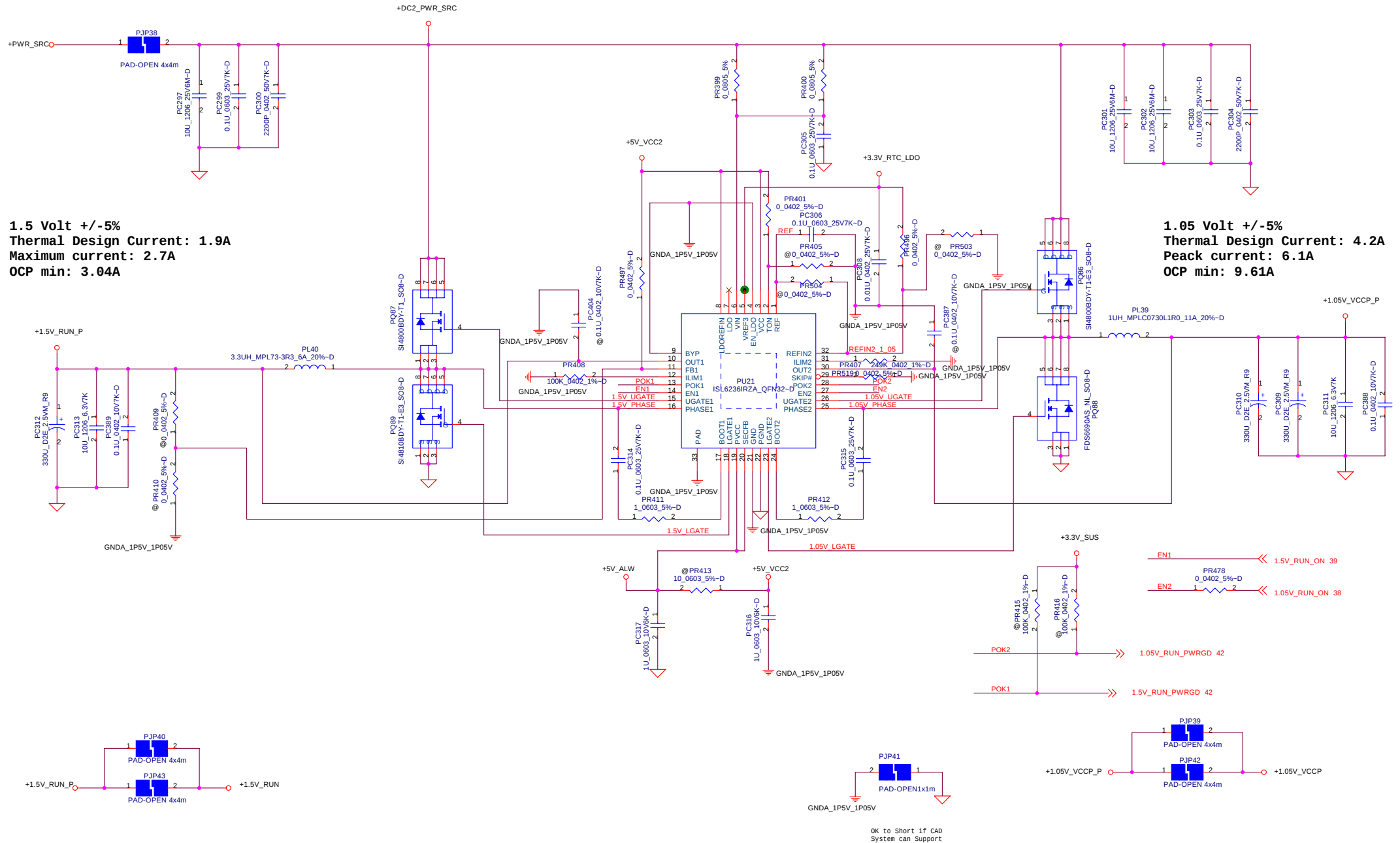
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Rev
0.0

1.5 Volt +/-5%
Thermal Design Current: 1.9A
Maximum current: 2.7A
OCP min: 3.04A

1.05 Volt +/-5%
Thermal Design Current: 4.2A
Peack current: 6.1A
OCP min: 9.61A



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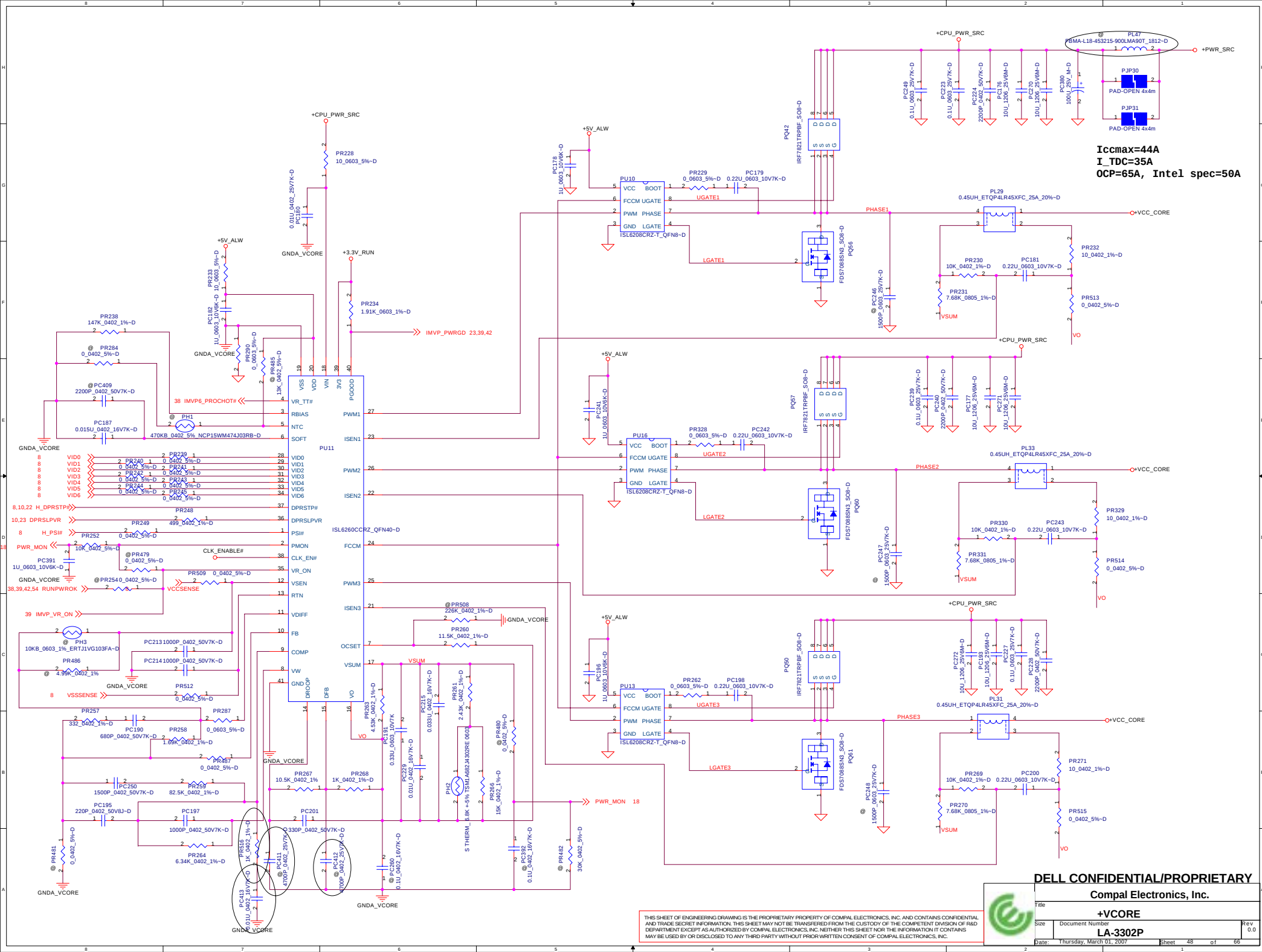


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+1.5V RUN / +1.05V VCCP

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	LA 2222B	0.0

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Iccmax=44A
I_TDC=35A
OCP=65A, Intel spec=50A

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+VCCORE

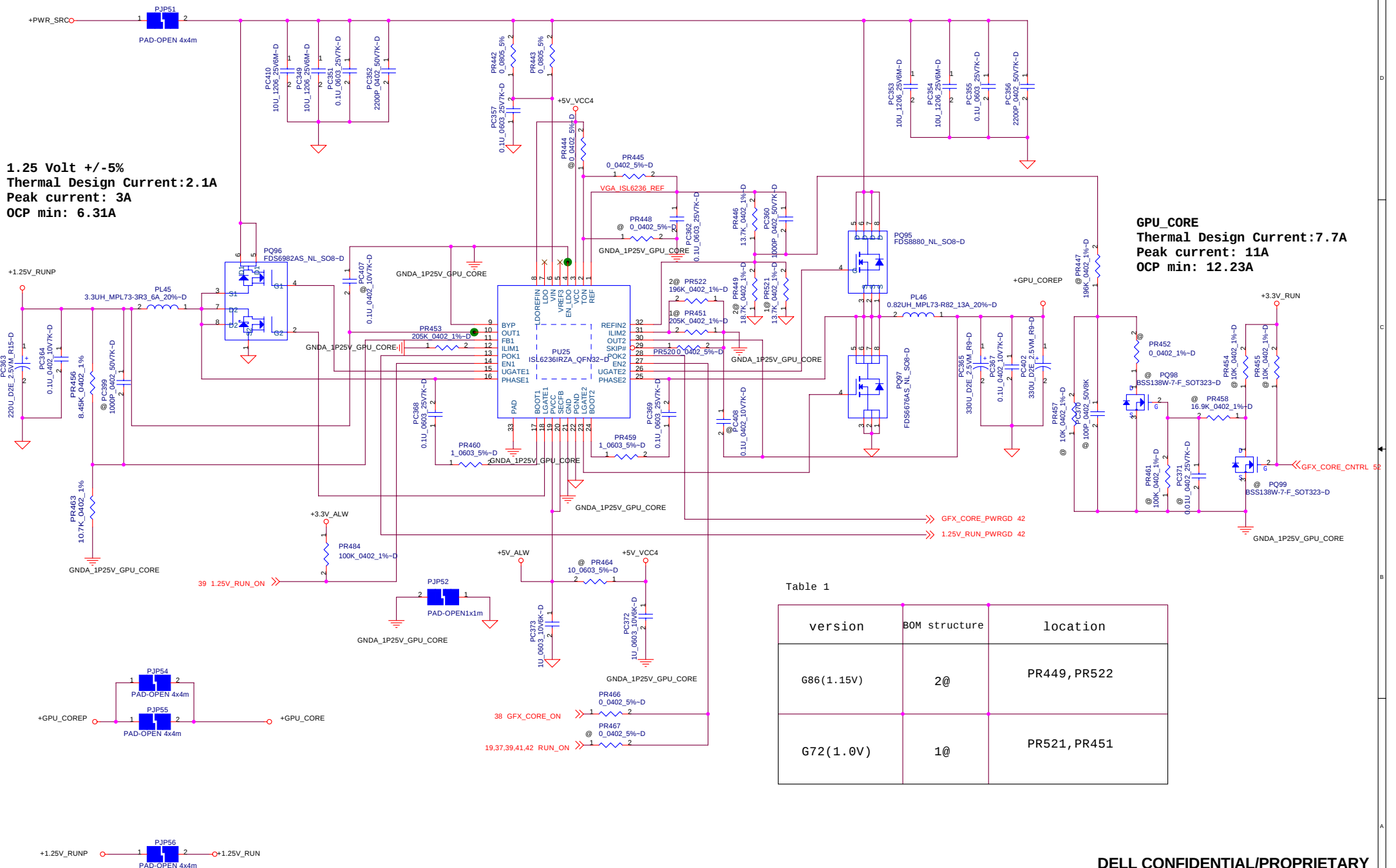
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1.25 Volt +/-5%
Thermal Design Current:2.1A
Peak current: 3A
OCP min: 6.31A

GPU_CORE
Thermal Design Current:7.7A
Peak current: 11A
OCP min: 12.23A



version	BOM structure	location
G86(1.15V)	2@	PR449, PR522
G72(1.0V)	1@	PR521, PR451

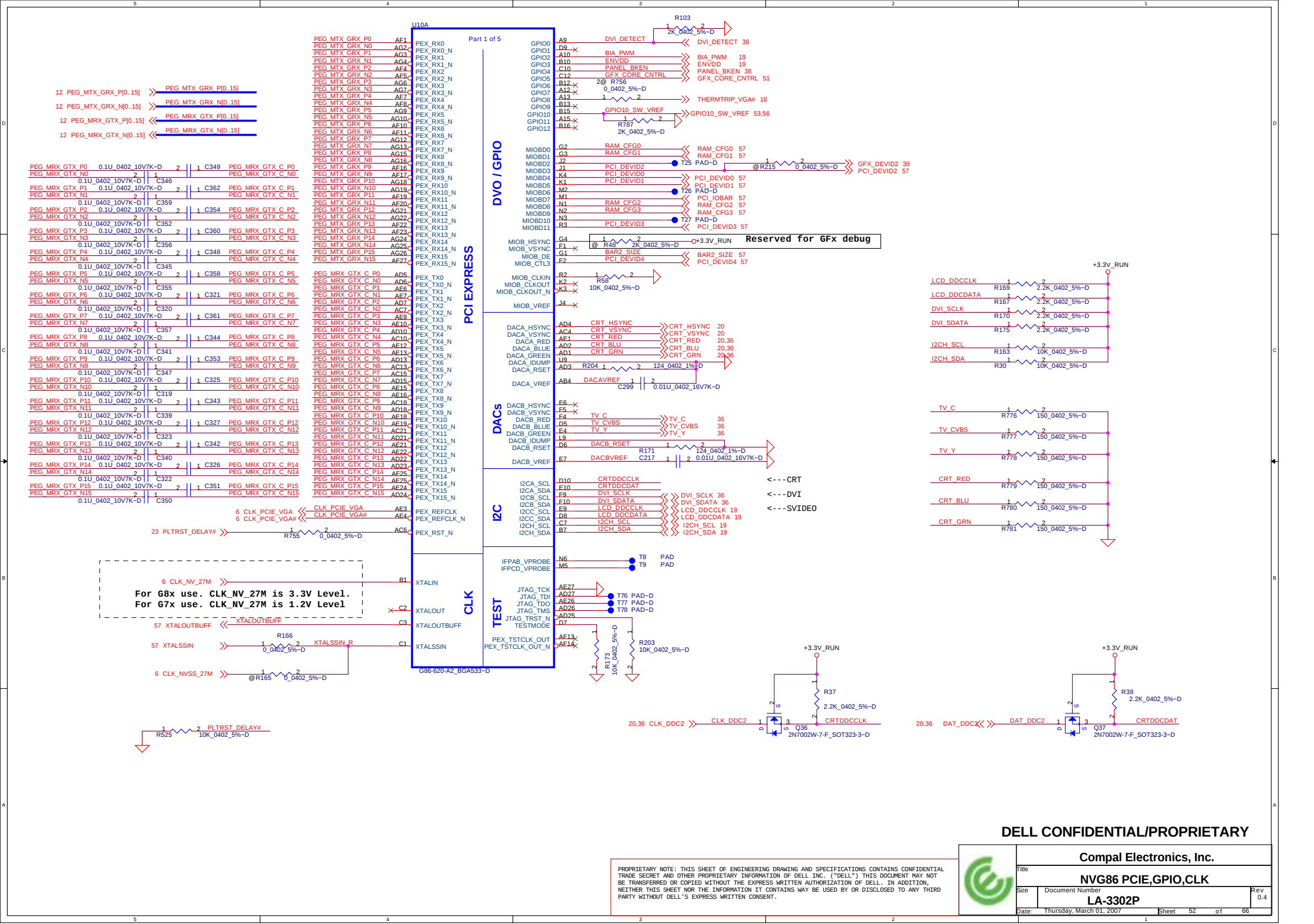
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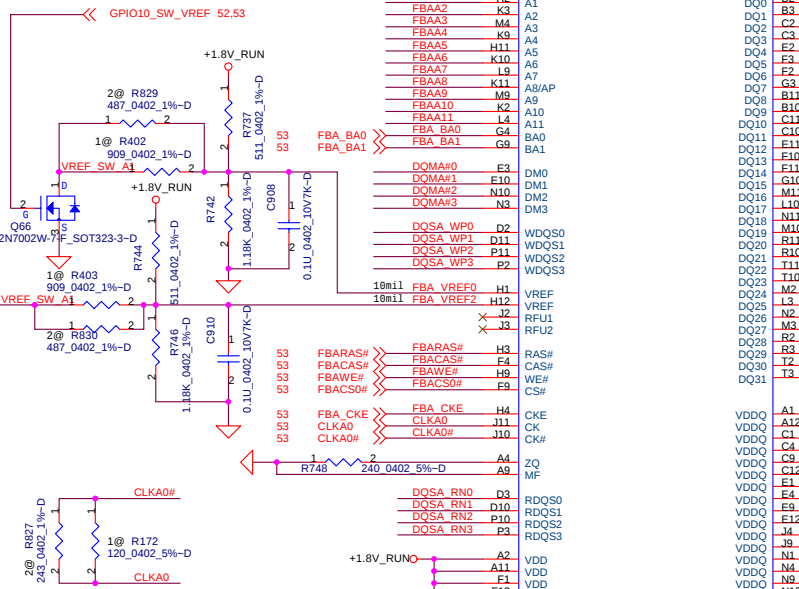
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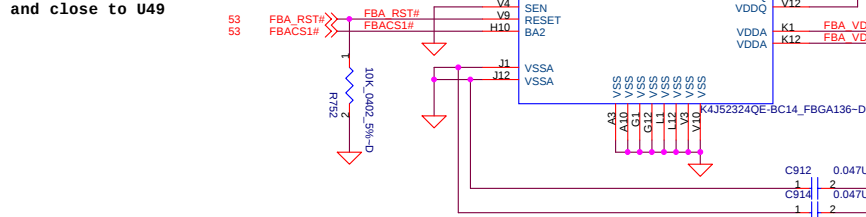






Populate R827 for G86
Populate R172 for G72MV.

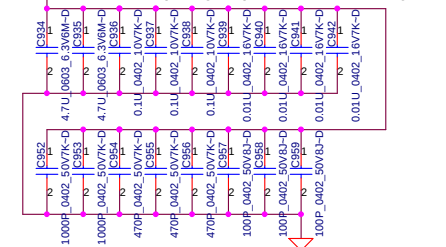
R172,R827 place overlap
and close to U49



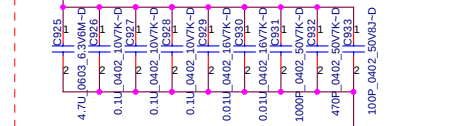
Place below decoupling caps close U11 VDD Pins



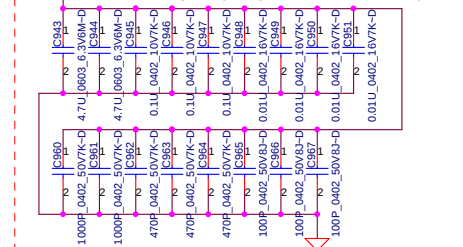
Place below decoupling caps close U11 VDDQ Pins



Place below decoupling caps close U14 VDD Pins



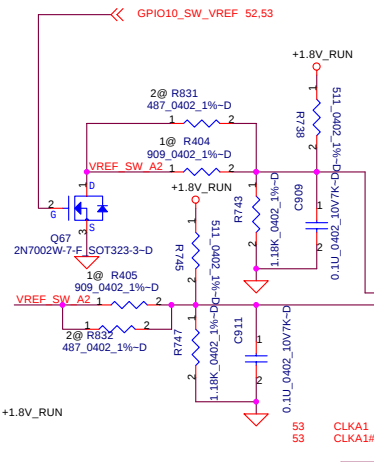
Place below decoupling caps close U14 VDDQ Pins


$$V_{REF} = V_{DDQ} \times R_b / (R_a + R_b)$$

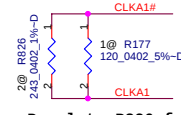
VREF=0.7 x VDDQ for G86 trun on, 0.4x VDDQ when trun off

VREF=0.7 x VDDQ for G72MV trun on, 0.5x VDDQ when trun off

R831,R832 for G86
R404,R405 for G72MV.
R831,R404 and R832,R405 place overlap



Change to 220ohm/100MHz



Populate R826 for G86
Populate R177 for G72MV.

R177,R826 place overlap
and close to U50

- FBAD[0:63] <<>> FBAD[0:63] 53
FBAA[0:11] <<>> FBAA[0:11] 53
FBBA[2:5] <<>> FBBA[2:5] 53
DQSA_WP[0:7] <<>> DQSA_WP[0:7]
DQSA_RN[0:7] <<>> DQSA_RN[0:7]
DQMA# [0:7] <<>> DQMA# [0:7] 53

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NVG86 External DDR

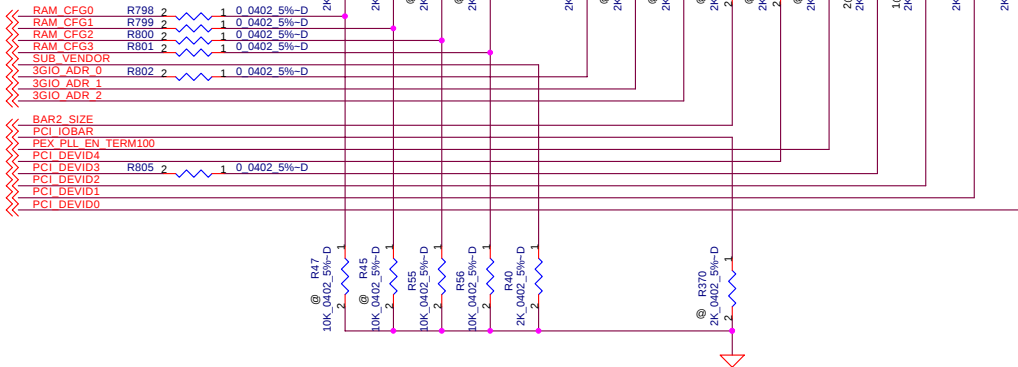
LA-3302P

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52 RAM_CFG0
52 RAM_CFG1
52 RAM_CFG2
52 RAM_CFG3
53 SUB_VENDOR
53 3GIO_ADR_0
53 3GIO_ADR_1
53 3GIO_ADR_2

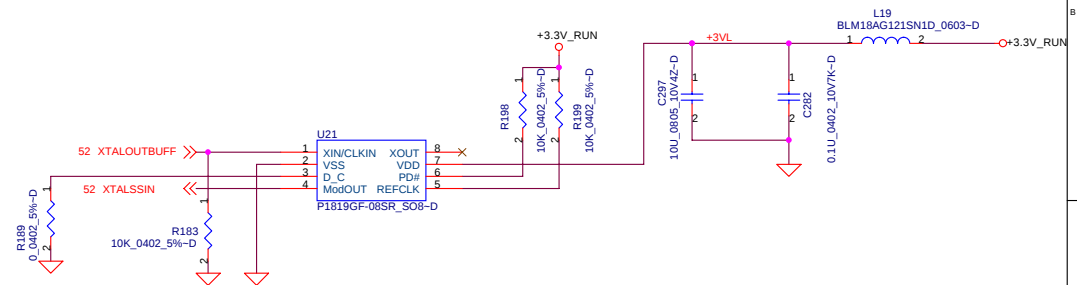
52 BAR2_SIZE
52 PCI_I0BAR
53 PEX_PLL_EN_TERM100
52 PCI_DEVID4
52 PCI_DEVID3
52 PCI_DEVID2
52 PCI_DEVID1
52 PCI_DEVID0



Device ID strapping				
	DEVID3	DEVID2	DEVID1	DEVID0
G72GLM	1	1	0	0
G72M	1	0	0	0
G72MV	0	1	1	1
G86MV	1	0	1	1

G72MV STRAPS

STRAPS	PIN	DESCRIPTION	Value
ROM_TYPE[1:0]	MI0BD10 MI0B_VSYNC	Parallel=00, SERIAL AT25F=01 DEFAULT, Serial SST45VF=10, LPC=11	01
SUB_VENDOR	MI0AD1	VBIOs on card (pull high) VBIOs with system B10S (pull down)	0
PEX_PLL_TERM	MI0AD0		0
RAM_CFG[3:0]	MI0BD0 MI0BD1 MI0BD8 MI0BD9	For GDDR1	
		8Mx32 DDR monolithic (64bit) 300MHz, 1.8V	0001
		8Mx32 DDR monolithic (32bit) 300MHz, 1.8V	1001
		8Mx32 DDR (Samsung K4D5323QF-GC) 300MHz, 1.8V	0010
		4Mx32 DDR generic (64bit) 1.8V I/O	0100
		4Mx32 DDR generic (32bit) 1.8V I/O	1100
	For GDDR3		
		Infineon 16Mx32 500MHz, 1.8V	0001
		Hynix 16Mx32 500MHz, 1.8V	0010
		Samsung 16Mx32 500MHz, 1.8V	0011



	S0
-1.75% (DOWN)	0
±0.875% (CENTER)	1

S0 Internal pull up

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hexainf@hotmail.com
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Item	Page#	Title	Date	Request Owner	Issue Description	Solution Description	Rev.
1	38	HW	08/2/2006	Compal	BID change to X01	Pop R108, depop R106	X01
2	18	HW	08/10/2006	Compal	Change SOT23 package to SOT323 package	Change Q102, Q59 to SOT323 package	X01
3	7	HW	08/21/2006	Compal	BITS issue WI86517 (S5 state back driver issue)	Change R324 pin1 connect from +3.3V_ALW to +3.3V_SUS	X01
4	41	HW	08/21/2006	Compal	Bits issue WI84312 (Derating issue)	Change R151 from 30 ohm to 75 ohm	X01
5	23	HW	08/21/2006	Compal	Bits issue WI86509	Populate R761 and change value from 100k to 10k. Change R761 pin1 connect from +3.3V_ALW to +3.3V_SUS	X01
6	39	HW	08/21/2006	Compal	Bits issue WI86511	Add R401 (100K) for signal BC_DAT pull up to +3.3V_ALW	X01
7	37	HW	08/21/2006	Compal	Bits issue WI86512	Change R131 to no-stuff and from 4.7k to 100k per SMSC	X01
8	23	HW	08/21/2006	Compal	Bits issue WI86516	R509 PU for SIO_EXT_SMI# change from +3.3V_ALW to +3.3V_SUS to prevent backdrive through the ICH in S4/S5	X01
9	38, 39	HW	08/21/2006	Compal	Bits issue WI86518	Swap PSID GPIO from ECE5018 pin 71 with MEC5025 ITP_DBRESET# pin 55	X01
10	38, 39	HW	08/21/2006	Compal	Bits issue WI86532	Swap BEEP (ECE5018 GPIOB[6]) with PLTRST_DELAY# (MEC5025 SGPIO46)	X01
11	18	HW	08/21/2006	Compal	Bits issue WI86752	Change pull-up rail for R773 from +5V_SUS to +3.3V_SUS	X01
12	21	HW	08/30/2006	Compal	Bits issue WI86530	Move SB_NB_PCIE_RST# to GPIO4/PIRQG# pinF12 per M08 design	X01
13	21	HW	09/7/2006	Compal	Bits issue WI86529	Move SB_WLAN_PCIE_RST# to GPIO3/PIRQF# U32 pin G11 per M08 direction, add test point T1 on pin F18	X01
14	39	HW	09/7/2006	Compal	Bits issue WI86376. Due to increase in number of payloads the BIOS is carrying	Change U23 from (ST M25P80 8M bit) to (MXIC MX25L1605AM2C 16M bit)	X01
15	54	HW	09/7/2006	Compal	Bits issue WI87262. Add depopulated soft start capacitor	Add C85 (470PF_0402) across R244	X01
16	43	HW	09/11/2006	Compal	Bits issue WI90535	Change Q5 to MMBT3906WT1G, R15 to 150 ohm. Add R638 on LED_WLAN_OUT# pull up to +3.3V_WLAN. Add R639 (10K ohm) in series on LED_WLAN_OUT#	X01
17	7	HW	09/14/2006	Compal	Briscoe ESD/EMI Improvement Requests on PT	Remove ITP port and just keep ITP test point	X01
18	34	HW	09/14/2006	Compal	Bits issue WI90713	No stuff C16	X01
19	43	HW	09/14/2006	Compal	Bits issue WI90712	Remove R73, R178, C192, and C193	X01
20	43	HW	09/14/2006	Compal	Bits issue WI90705	Add SMBus isolation circuit for WLAN, R640, R645, R660, R662, Q45, Q46	X01
21	34	HW	09/14/2006	Compal	Bits issue WI90696	JMINI1 connect to +3.3V_RUN. Removed C427	X01
22	12	HW	09/14/2006	Compal	Shunt caps on LVDS for improving WWAN	Add C181, C192, C193, C196, C207, C209 cross LVDS signals	X01
23	27	HW	09/14/2006	Compal	Bits issue WI90516	Remove C759 from mic amp bias circuit	X01
24	26	HW	09/14/2006	Compal	Bits issue WI90487	Populate R541 to cut BEEP level in half	X01

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Item	Page#	Title	Date	Request Owner	Issue Description	Solution Description	Rev.
25	18, 52	HW	09/14/2006	Compal	Bits issue WI90207	Connect THERMTRIP_VGA# from U10 pinB13 to U10 pin A13. Populate R186 for THERMTRIP_VGA# pull up	X01
26	43	HW	09/14/2006	Compal	Bits issue WI89637	Populate EMI Clips Clip1, Clip2, Clip3, Clip4, Clip6	X01
27	23	HW	09/14/2006	Compal	Bits issue WI89409	No stuff R516, add R690 (8.2K ohm) for pull up ICH8 pin AF22 to +3.3V_SUS	X01
28	25	HW	09/14/2006	Compal	Bits issue WI89407	Add Q68, Q69, R691, R692 for HDDC_EN and M0DC_EN circuits	X01
29	41	HW	09/14/2006	Compal	Bits issue WI89394	Change connect R765 pin1, R623 pin1, R621 pin1, R766 pin1, R637 pin1, R300 pin1 from +5V_ALW to +5V_ALW2	X01
30	37, 39	HW	09/14/2006	Compal	Bits issue WI89379	Change R387, R389 from 1M to 2.7K. Add R778, R779 for AUX_ON, AC_OFF	X01
31	39	HW	09/15/2006	Compal	Bits issue WI92249	Change R730 from 100K to 4.7K ohm	X01
32	57	HW	09/15/2006	Compal	Bits issue WI92188. The MIO_A_D0 signal has an internal pull-down in the GPU	Remove R39	X01
33	53, 55	HW	09/18/2006	Compal	Bits issue WI92289	U10 (NV86) pin F11, F12 connect to test point T89, T90 for testing and debug	X01
34	23	HW	09/18/2006	Compal	Bits issue WI92296	PLTRST_DELAY# move from ECE5018 GPOB[6] to ICH8 GPIO38	X01
35	34	HW	09/18/2006	Compal	Bits issue WI92287, WI90716	R660 and R662 connected to CLK_SCLK and CLK_SDATA.	X01
36	57, 37, 22, 33, 28, 19, 20	HW	09/18/2006	Compal	EMI solutions	Populate SSCG U21, R189, R198, R199, L19, C297, C282, R166. depopR165. Populate RS232 C152, 153, 154, 155, 156, 157, 158, 159. Resume ICH_AZ_MDC_BITCLK C656, R123, C128. Add R790, R791, C232, C267. Change L63, L65 from 0603size to 0805size. Add C309, C316 for LOM. Add C427, C463 for LVDS. Add fuse F3, R792 for CRT. Populate C660, R545 (10 ohm), C721 (10P)	X01
37	23, 36	HW	09/18/2006	Compal	Bits issue WI92298	Move SIO_EXT_SCI# from to ICH8 GPIO11/SMBALERT# pin AG22 to GPO12 pin AC19. Remove D22 and R761 and net DOCK_DET#	X01
38	23	HW	09/18/2006	Compal	Bits issue WI92299	ICH8 Pin AG22 tie to LOM_ICH_SMBALERT#. Add R793 (0 ohm) series on LOM_ICH_SMBALERT# and LOM_SMB_ALERT#. Change R730 pull up rail from +3.3V_ALW to +3.3V_LAN. Add R807 pull up to +3.3V_SUS for LOM_ICH_SMBALERT#	X01
39	39	HW	09/18/2006	Compal	Bits issue WI92301	Move ALW_PWRGD_3V_5V from MEC5025 pin 18 to MEC5025 pin 29. Remove 3.3V_5V_SUS_PWRGD from MEC5025 pin 29	X01
40	38, 39	HW	09/18/2006	Compal	Bits issue WI92305	Swap DOCK_SMB_PME and DOCK_SMB_ALERT# from MEC5025 pin3 and ECE5028 pin76	X01
41	39, 42	HW	09/18/2006	Compal	Bits issue WI92308	Removed 3.3V_LAN_PWRGD from MEC5025 KS015/GPI05. Remove U52, Q83, D29, R89, R98, R381, C784, C182, C183, C184	X01
42	39	HW	09/18/2006	Compal	Bits issue WI92312	Add R795 (10K ohm) pull down for MEC5025 pin 14	X01
43	29	HW	09/19/2006	Compal	EMI issue	Populate R671~R678 and C866~C869. Change L69~L76 from 24NH to 36NH inductor	X01
44	27	HW	09/19/2006	Compal	Bits issue WI90510	Add R796, R797 (0ohm) between L47/L48 and C728/C730	X01
45	57	HW	09/20/2006	Compal	EMI request	Add R798~R803 for strap damping	X01



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46	18	HW	09/20/2006	Compal	Bits issue WI92860	Depop Q39 and R427	X01
47	28	HW	09/20/2006	Compal	Bits issue WI92858	Change R669 to from 1.15K to 1.13K. Depop C771 & C772. Change C861 and C862 to 22pF	X01
48	38	HW	09/20/2006	Compal	Bits issue WI92857	Add no-stuff series 0-ohm for ITP_DBRESET# on ECE5028	X01
49	33	HW	09/21/2006	Compal	Bits issue WI93157	Remove R586 and make JMDC pin2 NC	X01
50	34	HW	09/21/2006	Compal	Bits issue WI93158	Depop Q45, Q46	X01
51	6	HW	09/25/2006	Compal	Bits issue WI93403	C484 change to 33pF, C861/C862 change to 22pF	X01
52	29	HW	09/26/2006	Compal	Bits issue DF86424	No Populate C866-C869/R671-R678	X01
53	40	HW	09/26/2006	Compal	EMI request	Add D37-D40 for stick point signals	X01
54	32	HW	09/27/2006	Compal	Bits issue DF94094	Add FUSE4,FUSE5	X01
55	9	HW	09/28/2006	Compal	Bits issue WI94923	C329,C330 chagne back to 10 0805 X6S	X01
56	18	HW	10/05/2006	Compal	Bits issue WI94892	Populate R771, C750, R772, Q102, R773	X01
57	30	HW	10/05/2006	Compal	Bits issue WI95910	Change R603 from 6.2k to 5.9k. Change C805 from 820pF to 270pF	X01
58	38, 23 27, 6	HW	10/05/2006	Compal	Bits issue WI95932	No stuff R227, R221, C89, C93, C97, c401, C92, r72, C90, C94. No stuff C775-C781, C785. No stuff R514 (no iAMT). Populate R515.	X01
59	36	HW	10/14/2006	Dell	Bits issue WI97539	Added signal DOCK_DET# to JDOCKBpin137, pin205 and Q3pin2	X02
60	9	HW	10/17/2006	Dell	Bits issue WI97837	Add 0.1 uf (0402) caps on +Vcc_Core to Gnd. Four total, bottom of board. (C870 ~ C873)	X02
61	23	HW	10/18/2006	Dell	Bits issue WI98222 (Change for ASF2.0 due to ICH8M errata)	1. No stuff R502, R503 2. Connect the pad of R503.2 to the pad of R498.2 3. Connect the pad of R502.1 to the pad of R499.2	X02
62	38	HW	10/24/2006	Dell	Board ID Changed to X02	Populated R106, R107. Depopulated R108, R109.	X02
62	38	HW	10/24/2006	Dell	Bits issue WI98660	The DevID for G86 on Briscoe needs to be updated to 1011	X02
63	23	HW	11/16/2006	Dell	Bits issue WI104573	Add R816,C874 for USB_IDE#. R817,C875 for SIO_EXT_WAKE#. R819,C876 for PCIE_MCARD1_DET#. R820,C878 for USB_MCARD1_DET#. R818,C877 for USB_MCARD2_DET#. Remove net RSVD_GPI06 and R513	X02
64	6, 23, 34	HW	11/16/2006	Dell	Bits issue WI103311	Change R309 from 8.2K to 2.2K. No stuff R820. No stuff R550	X02
65	39	HW	11/18/2006	Dell	Bits issue WI103986	Change C379 from 22pF to 33pF per KDS X'tal report	X02
66	25, 41	HW	11/20/2006	Compal	Bits issue WI105207	Change net name from +5V_ALW2 to +3.3V_ALW2 at R618.1, R626.1, R623.1, R621.1, R766.1, R765.1, R637.1, R300.	X03

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67	28	HW	11/21/2006	Dell	Bits issue WI105200	Change L64,L66,L67,L68 from BLM18AG601SN1D to BK1608LM182. Change R668 to L88 BK1608LM182. Change L63, L65 from BLM21AG601SN1D to BK2125LM182.	X02
68	6, 54, 57	HW	11/21/2006	Dell	Bits issue WI105712	Depop R697, change R286 to 0 ohm. Pop L53, depop L16. Pop L27, C314, C315. Depop L20, L21, pop L54, L55. Depop L17.	X02
69	38, 39	HW	11/21/2006	Dell	Bits issue WI105754	Change R794 pin1 from +5V_ALW to +3.3V_ALW.	X02
70	26	HW	11/21/2006	Dell	Bits issue WI105758. Updates for potential Back Drive	Change R245 pin1 from +3.3V_ALW to +5V_ALW	X02
71	21, 23, 34	HW	12/1/2006	Dell	Bits issue WI106999	Add 100kohm resistor R721 between U35 pin 40 and +3.3V_RUN and 1000pF cap C759	X02
72	41	HW	12/1/2006	Dell	Bits issue WI107466. +2.5V_LAN in-rush current test fai.	Please populate R820 with a 4.7k-ohm resistor. Move signal PCIE_MCARD2_DET# from ICH8m GPIO20 pinAE11 to PIRQH#/GPIO5 pinB3. Delete R457 and net ICH_GPIO5_PIRQH#. Populate R550	X02
73	6	HW	12/5/2006	Dell	Bits issue WI107881	Populate C208	X02
74	27	HW	12/6/2006	Dell	Bits issue WI107896	Change R286 from 0 ohm to 33 ohms	X02
75	36, 38	HW	12/6/2006	Dell	Bits issue WI108259. Per M08 GPIO map rev A15 Change list	Change R554 from 10K to 0 ohm	X02
76	9	HW	12/6/2006	Dell	Bits issue WI108223	Change net DOCK_SMB_PME to DOCK_SMB_PME#	X02
77	52	HW	12/12/2006	Dell	Bits issue WI109622. Per NB8M PUN document	Change C177, C179, C178, C366, C338, C365 to EEFSX0D221E7 220uF	X02
78	55	HW	12/13/2006	Dell	Bits issue WI109627	Change R35 from 60.4 ohm to 40.2 ohm	X02
79	39	HW	12/14/2006	Dell	Bits issue WI110179	Change R174 from 40.2 ohm to 30 ohm	X02
80	27	HW	12/15/2006	Dell	Bits issue WI110158	Add EC_FLASH_PAD pin1 connect to +3.3V_ALW, pin2 connect to R76 pin1 and R80 pin1	X02
81	26	HW	12/18/2006	Dell	Bits issue WI110749	Add R822 (1M_0402) from Pin 10 (C1P) pin of MAX9789A to ground	X02
82	29	HW	12/20/2006	Dell	Bits issue WI111288	Add R823 (10K_0402) to ground on pin 47 of STAC9205 (U37)	X02
83	12, 23, 28	HW	12/25/2006	Dell	Change AC Coupling Cap SPEC for PCIE	Change R683 from 150ohms to 110 ohms, R684 from 150ohms to 200ohms	X02
84	54, 55	HW	1/5/2007	Dell	Bits issue WI113179	Change C500-C531, C664, C666-C670, C851, C853 from 0.1uF Y5V to 0.1uF X7R	X02
85	56	HW	1/5/2007	Dell	Bits issue WI113180	Change R174 to 24.9 ohm for G86, Add R824 40.2 ohm for G72. Change R35 to 45.3 ohm G86, add R825 60.4 ohm for G72MV	X03
86	53, 56	HW	1/5/2007	Dell	Bits issue WI113227	Add R826, R827 243 ohm for G86	X03
87	38	HW	1/5/2007	Dell	Chagne Board ID to X03	Add R828, R829, R830, R831, R832 487 ohm for G86	X03
88	6	HW	1/8/2007	Dell	Bits issue WI113588	Populate R108, de-pop R106	X03
						Change U10 value to G86-620-A2. Add R833=147 ohm with R697 use 1@ for G72. R286=33 ohm use 2@ for G86. Change R48 note to "Reserved for GFx debug".	X03



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89	38	HW	1/26/2007	Dell	Bits issue WI115658. M08 GPIO map rev A16 change	Change ECE5028 GPIOF4 from BID2 to CHIPSET_ID.	X03
90	23	HW	2/12/2007	Dell	Bits issue WI121957	Add R834 (1M_0402_1%) for ICH_LAN_RST#	X03
91	27	HW	2/12/2007	Dell	Bits issue WI121438	Change R565 from 10K to 100k ohm	X03
92	41	HW	2/12/2007	Dell	Bits issue DF116813	Depop C194, changed C815 from 4700pF to 2200pF	X03
93	54	HW	2/14/2007	Dell	Modify pop option symbol for G72M/G86M power bead	L53,L27,L55,L54, with 2@, L16,L17,L21, L20, with 1@	X03
94	57	HW	2/14/2007	Dell	Modify NV strap table	Change GDDR3 table from 500 MHz to 700 MHz	X03
95	18	HW	2/26/2007	Dell	Bits issue WI124164	populate C640 = 10uF for G72MV. Add 1@ for C640	X03
96	54 57	HW	2/26/2007	Dell	Bits issue WI124408	Add note "Populate C251, C255 for G86 and G72 solution per Nvidia". Add 2@ for C314, C315, R805 and R57. Add 1@ for R49.	X03
97	54	HW	2/27/2007	Dell	Bits issue WI123608	Change C233 from X5R to X7R	X03
98	23	HW	2/27/2007	Dell	Bits issue WI125173. Per Intel's latest recommendation	Change R834 from 1M to 10K	X03
99	54	HW	2/28/2007	Dell	Bits issue WI123608	Change C233 back to X5R	X03
100	18 52	HW	2/28/2007	Dell	Bits issue WI124613. Need to connect THERMTRIP_VGA to the thermal sensor for G86	Add 2@ for R756, R187, Q76, C203	X03
101	18	HW	3/1/2007	Dell	Bits issue WI125873. Populate circuit for THERMTRIP_MCH#	Populate R427 and Q39	X03
102	27	HW	3/7/2007	Dell	Bits issue WI127300	Change U40 from 74AHC1G08 to 74AHCT1G08	X03

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Item	Page#	Title	Date	Request Owner	Issue Description	Solution Description	Rev.
1	48/50	PWR	9/14	Elick	change the AL CAP to 2000hr	change PC380 from SF10004M08L to SF000000S8L. change PC381 from SF10004M08L to SF000000S8L. change PC382 from SF10004M08L to SF000000S8L.	0.1
2	45	PWR	9/14	DELL	change to correct parts for 15ALW	change PD55 from SCSB717F08L to SCS00001U8L. change PD56 from SCSB717F08L to SCS00001U8L.	0.1
3	48	PWR	9/14	DELL	change to PSL of DELL	change PH2 from SL20000030L to SL200000F8L	0.1
4	44	PWR	9/14	DELL	change to PSL of DELL	change PL1 from SM01001680L to SM010008U0L.	0.1
5	44	PWR	9/14	DELL	change to PSL of DELL	change PL2 from SM01001418L to SM010009C8L. change PL34 from SM01001418L to SM010009C8L.	0.1
6	46	PWR	9/14	DELL	BITS-WI89364 The 0.9V_DDR_VTT_PWRGD net is not used at the MEC5025. The 0.9V_DDR_VTT_PWRGD net should be no connect at the MEC5025 pin 73.	remove PR437, PR438, PR441, PQ93 and PQ94.	0.1
7	45	PWR	9/14	DELL	BITS-WI91011 change to correct current limits	Change PR383 from 124K(SD03412438L) to 150K(SD03415038L). Change PR382 from 187K(SD03418738L) to 226K(SD03422638L).	0.1
8	47	PWR	9/14	DELL	BITS-WI91278 following DELL rule	Depopulate PR415 and PR416 resistors.	0.1
9	49	PWR	9/14	DELL	BITS-WI91289 be compliant with the reference schematic.	Change PR274 from 4.7 ohm(SD000006T8L) to 33 ohm(SD014330A8L). Populate PR373 and PD54.	0.1
10	51	PWR	9/14	DELL	BITS-WI91295 Implement changes to 1.25V_RUN and GPU Core regulators	Add PC410 10uF, 1206, 25V at the input rail (+PWR_SRC) of the 1.25V_RUN regulator. Change PR460 from 0 ohm(SD01300008L) to 1 ohm(SD013100B8L). Change PR459 from 0 ohm (SD01300008L) to 1 ohm(SD013100B8L). Change PR449 ground connection from AGND to PGND.	0.1
11	47	PWR	9/14	DELL	BITS-WI91372 following DELL rule	Change PR408 from 75K(SD03475028L) to 82.5K(SD00000278L).	0.1
12	44	PWR	9/14	DELL	BITS-WI91682 DC IN schematic changes.	Change PL1 from SM01001680L to SM010008U0L. Change PQ100 from SI2301BDS(SB923010020) to PQ100A depopulated IMD2A(SB000009N8L). Change PQ101 from SI2301BDS(SB923010020) to PQ100B depopulated IMD2A(SB000009N8L). Change PR12 from 10K,0603(SD01310028L) to 4.7K,0805(SD00247018L).	0.1
13	45	PWR	9/14	DELL	BITS-WI90985 following DELL rule	Change PC285 pin 2 pad connection from PGND to AGND.	0.1
14	45	PWR	9/14	DELL	BITS-WI90988 Change PQ83 from FDS8880 to BSC079N03SG PPAK	Change PQ83 from SB000004U8L to SB000004D8L.	0.1
15	51	PWR	9/15	DELL	BITS-WI92173 correct the current limit on GPU CORE regulator	Change PR451 from 140K(SD03414038L) to 182K(SD03418238L)	0.1

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16	51	PWR	9/15	DELL	BITS-WI92161 correct the current limit on 1.25V_RUN regulator.	Change PR453 from 140K(SD03414038L) to 205K (SD03420538L)	0.1
17	46	PWR	9/15	DELL	BITS-WI91932 correct the current limit on 1.8V output	Change PR202 from 61.9K(SD03461928L) to 100K (SD03410038L)	0.1
18	46	PWR	9/18	DELL	BITS-WI92459 follow BITS of DELL	change PR193 to be populate. change PR506 to be populate. change PR505 to be depopulate.	0.1
19	48	PWR	9/18	DELL	BITS-WI92462 improve transients at load dump. and reduce jittering.	Add depopulate PR516(SD03410018L) and depopulate PC413(SE076103K8L) between pin 9 of PU11 and AGND. Add depopulated PC411(SE075472K8L),4700pF between pin 14 of PU11 and AGND Add depopulated PC412(SE075472K8L),4700pF between pin 15 of PU11 and AGND	0.1
20	51	PWR	9/18	DELL	BITS-WI87245 PWRGD signals are reversed coming from the wrong side of the IC.	Change the node name at pin 13 of PU25 from GFX_CORE_PWRGD to 1.25V_RUN_PWRGD. Change the node name at pin 28 of PU25 from 1.25V_RUN_PWRGD to GFX_CORE_PWRGD . Remove +3.3V_RUN node connected to pin 2 of PR462. Remove +3.3V_ALW node connected to pin 1 of PR483. Remove +3.3V_ALW node connected to pin 1 of PR450. Remove totally PR462 pad, PR483, PR450.	0.1
21	51	PWR	9/20	Elick	change GPU_CORE voltage	change PR446 from 10k to 13.7k(SD03413728L)	0.1
22	44	PWR	9/21	DELL	BITS-WI91682 change PL1 from BK1608HM to BLM18BD102SN1D.	change PL1 from SM010008U0L to SM010007C8L.	0.1
23	48/50	PWR	9/21	DELL	BITS-WI87563 change populate PC380 from 25CE100AX to 25CE100LS change PC381 from 25CE100AX to 25CE100LS change PC382 from 25CE100AX to 25CE100LS	change populate PC380 from SF000000S8L to SF000000T8L. change PC381 from SF000000S8L to SF000000T8L. change PC382 from SF000000S8L to SF000000T8L.	0.1
24	49	PWR	9/29	DELL	match Maxim's response time of ICM input to comparator.	change PR361 from 0 0hm (SD02800008L) to 8.45K (SD000000068L). change PC254 from 0.01uF 25V (SE068103K8L) to 0.1uF 16V (SE076104K8L).	0.1
25	49	PWR	9/29	DELL	ICM is voltage source and does not need this component.	depopulate PR150.	0.1
26	49	PWR	9/29	DELL	Increase BW from 20kHz to 25kHz while maintaining 80degrees phase margin.	change PR148 from 4.7K (SD03447018L) to 10K (SD03410028L).	0.1
27	49	PWR	9/29	DELL	following DELL rule	depopulate PD54 and PR373	0.1
28	48	PWR	10/27	DELL	Add bead to connect +PWR_SRC to +CPU_PWR_SRC	Add PL47(SM01002078L) to parallel PJP30.	0.2

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29	45, 46, 47, 51	PWR	10/27	DELL	BITS-WI99895 This is to add an optional ultrasonic mode in case the regulators experience an audible noise.	Add PR517 0 ohm 0402(SD02800008L) between pin 29 of PU20 and AGND . Add PR519 0 ohm 0402(SD02800008L) between pin 29 of PU21 and AGND . Add PR520 0 ohm 0402(SD02800008L) between pin 29 of PU25 and AGND . Add PR518 0 ohm 0402(SD02800008L) between pin 26 of PU6 and AGND .	0.2
30	49	PWR	10/27	DELL	BITS: WI102600 Change PR148 from 10K_0402_1% to 2.2K_0402_5%	change PR148 from 10k 0402 1%(SD03410028L) to 2.2k 0402 5%(SD02822018L)	0.3
31	45	PWR	11/20	DELL	BITS-WI105406 Add node name +3.3V_ALW2 for the trace connected to the pin 5 (VREF3) of PU20. Populate PC285 with 0.1uF cap.	Add node name +3.3V_ALW2 between pin5 of PU20 and PC285. Populate PC285.	0.3
32	49	PWR	12/06	DELL	BITS-WI106278 make sure that PC113, PC114 and PC379 are X5R/X7R caps, need to stuff PC379.	change PC379 is populated.	0.3
33	48	PWR	12/06	DELL	BITS-WI108229 Change PC187 from 10nF to 15nF. Change PR258 from 2.21K to 1.69K. Populate PR516 with 1K resistor. Populate C413 with 0.01uF.	change PR187 from 10nF(SE076103K8L) to 15nF(SE076153K8L). change PR258 from 2.21K(SD03422118L) to 1.69K(SD00000JB8L). populate PC413. populate PR516.	0.3
34	51	PWR	01/04	ELICK	EMI CLK issue	Add PL3 to parallel PJP54. add PC414 to connect between GPU_CORE to GND. add PC415 to connect between GPU_CORE to GND.	0.3
35	49	PWR	01/25	ELICK	change to new part number for PSL	change PR138 from SD021100D8L to SD021100D3L(S RES 1W .01 +-1% 2512 FOR M08 PROJECTS) change PR145 from SD021100D8L to SD021100D3L(S RES 1W .01 +-1% 2512 FOR M08 PROJECTS)	0.4
36	44	PWR	01/26	ELICK	change bead to 9A 1812 in DC-IN.	change PL2 from SM010009C8L(TAIY0 FBMJ4516HS720NT 1806) to SM01000BI0L(KC FBCA-K5B-302340-L1-T 1812). change PL32 from SM010009C8L(TAIY0 FBMJ4516HS720NT 1806) to SM01000BI0L(KC FBCA-K5B-302340-L1-T 1812).	0.4
37	45/47/51	PWR	02/05	DELL	BITS-WI119950 Increase current limits for 3.3V, 1.5V and GPU_CORE regulators.	change PR382 from 226K to 267k (SD02822018L). Change PR408 from 82.5K to 100K(SD03410038L). Change PR451 from 182K to 205K(SD03420538L) .	0.4
38	49	PWR	02/06	DELL	additional 1206 resistor on +VCHGR for Maxim solution.	add an unpopulation PR522 (1.8K 1206 1%(SD00000JN8L))between +VCHGR to PGND.	0.4
39	49	PWR	02/12	DELL	delete 1206 resistor on +VCHGR not to implement for Maxim solution.	delete an unpopulate PR520 (1.8K 1206 1%(SD00000JN8L))between +VCHGR to PGND.	0.4

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